- Low-Cost, High-Performance Fixed-Point DSP – TMS320C6411
 - 3.3-ns Instruction Cycle Time
 - 300-MHz Clock Rate
 - Eight 32-Bit Instructions/Cycle
 - Twenty-Eight Operations/Cycle
 - 2400 MIPS
 - Fully Software-Compatible With TMS320C62x™
- VelociTI.2™ Extensions to VelociTI™
 Advanced Very-Long-Instruction-Word
 (VLIW) TMS320C64x™ DSP Core
 - Eight Highly Independent Functional Units With VelociTI.2™ Extensions:
 - Six ALUs (32-/40-Bit), Each Supports
 Single 32-Bit, Dual 16-Bit, or Quad
 8-Bit Arithmetic per Clock Cycle
 - Two Multipliers Support
 Four 16 x 16-Bit Multiplies
 (32-Bit Results) per Clock Cycle or
 Eight 8 x 8-Bit Multiplies
 (16-Bit Results) per Clock Cycle
 - Non-Aligned Load-Store Architecture
 - 64 32-Bit General-Purpose Registers
 - Instruction Packing Reduces Code Size
 - All Instructions Conditional
- Instruction Set Features
 - Byte-Addressable (8-/16-/32-/64-Bit Data)
 - 8-Bit Overflow Protection
 - Bit-Field Extract, Set, Clear
 - Normalization, Saturation, Bit-Counting
 - VelociTI.2™ Increased Orthogonality
- L1/L2 Memory Architecture
 - 128K-Bit (16K-Byte) L1P Program Cache (Direct Mapped)
 - 128K-Bit (16K-Byte) L1D Data Cache (2-Way Set-Associative)
 - 2M-Bit (256K-Byte) L2 Unified Mapped RAM/Cache (Flexible RAM/Cache Allocation)
- 32-Bit External Memory Interface (EMIF)
 - Glueless Interface to Asynchronous Memories (SRAM and EPROM) and Synchronous Memories (SDRAM, SBSRAM, ZBT SRAM, and FIFO)
 - 512M-Byte Total Addressable External
 Memory Space

- Enhanced Direct-Memory-Access (EDMA)
 Controller (64 Independent Channels)
- Host-Port Interface (HPI)
 - User-Configurable Bus Width (32-/16-Bit)
 - Access to Entire Memory Map
- 32-Bit/33-MHz, 3.3-V Peripheral Component Interconnect (PCI) Master/Slave Interface Conforms to PCI Specification 2.2
 - Access to Entire Memory Map
 - Three PCI Bus Address Registers:
 Prefetchable Memory
 Non-Prefetchable Memory I/O
 - Four-Wire Serial EEPROM Interface
 - PCI Interrupt Request Under DSP Program Control
 - DSP Interrupt Via PCI I/O Cycle
- Two Multichannel Buffered Serial Ports (McBSPs)
 - Direct Interface to T1/E1, MVIP, SCSA Framers
 - ST-Bus-Switching Compatible
 - Up to 256 Channels Each
 - AC97-Compatible
 - Serial Peripheral Interface (SPI)
 Compatible (Motorola™)
- Three 32-Bit General-Purpose Timers
- Sixteen General-Purpose I/O (GPIO) Pins
 - Programmable Interrupt/Event
 Generation Modes
- Flexible PLL Clock Generator
- IEEE-1149.1 (JTAG†)
 Boundary-Scan-Compatible
- 532-Pin Ball Grid Array (BGA) Package (GLZ Suffix), 0.8-mm Ball Pitch
- 0.12-μm/6-Level Metal Process
 CMOS Technology
- 3.3-V I/Os, 1-V Internal

Please be aware that an important notice concerning availability, standard warranty, and use in critical applications of Texas Instruments semiconductor products and disclaimers thereto appears at the end of this data sheet.

TMS320C62x, VelociTI.2, VelociTI, and TMS320C64x are trademarks of Texas Instruments. Motorola is a trademark of Motorola, Inc.

TIFEE Standard 1149.1-1990 Standard-Test-Access Port and Boundary Scan Architecture.

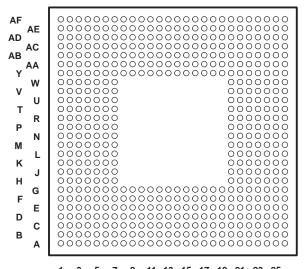


SPRS196 - MARCH 2002

Table	of Contents
GLZ BGA package (bottom view)	recommended operating conditions 58
description	electrical characteristics over recommended ranges of supply voltage and operating case temperature . 59
device compatibility	parameter measurement information 60
functional block and CPU (DSP core) diagram 6	input and output clocks
CPU (DSP core) description 7	asynchronous memory timing
memory map summary	programmable synchronous interface timing 69
peripheral register descriptions	synchronous DRAM timing
EDMA channel synchronization event	HOLD/HOLDA timing
interrupt sources and interrupt selector	BUSREQ timing 81
signal groups description	reset timing 82
device configurations	external interrupt timing 84
multiplexed pins	host-port interface (HPI) timing 85
debugging considerations	peripheral component interconnect (PCI) timing 90
terminal functions	multichannel buffered serial port (McBSP) timing 93
development support	timer timing 104
documentation support	general-purpose input/output (GPIO) port timing 105
clock PLL	JTAG test-port timing
power-supply sequencing	mechanical data
absolute maximum ratings over operating case temperature range	

GLZ BGA package (bottom view)

GLZ 532-PIN BALL GRID ARRAY (BGA) PACKAGE (BOTTOM VIEW)





SPRS196 - MARCH 2002

description

The TMS320C64x™ DSPs (including the TMS320C6411 device) are the highest-performance fixed-point DSP generation in the TMS320C6000™ DSP platform. The TMS320C6411 (C6411) device is based on the second-generation high-performance, advanced VelociTl™ very-long-instruction-word (VLIW) architecture (VelocTI.2™) developed by Texas Instruments (TI), making these DSPs an excellent choice for multichannel and multifunction applications. The C64x™ is a code-compatible member of the C6000™ DSP platform.

With performance of up to 2400 million instructions per second (MIPS) at a clock rate of 300 MHz, the C6411 device offers cost-effective solutions to high-performance DSP programming challenges. The C6411 DSP possesses the operational flexibility of high-speed controllers and the numerical capability of array processors. The C64x™ DSP core processor has 64 general-purpose registers of 32-bit word length and eight highly independent functional units—two multipliers for a 32-bit result and six arithmetic logic units (ALUs)— with VelociTI.2™ extensions. The VelociTI.2™ extensions in the eight functional units include new instructions to accelerate the performance in key applications and extend the parallelism of the VelociTI™ architecture. The C6411 can produce two 32-bit multiply-accumulates (MACs) per cycle for a total of 600 million MACs per second (MMACS), or eight 8-bit MACs per cycle for a total of 2400 MMACS. The C6411 DSP also has application-specific hardware logic, on-chip memory, and additional on-chip peripherals similar to the other C6000™ DSP platform devices.

The C6411 uses a two-level cache-based architecture and has a powerful and diverse set of peripherals. The Level 1 program cache (L1P) is a 128-Kbit direct mapped cache and the Level 1 data cache (L1D) is a 128-Kbit 2-way set-associative cache. The Level 2 memory/cache (L2) consists of a 2-Mbit memory space that is shared between program and data space. L2 memory can be configured as mapped memory, cache, or combinations of the two. The peripheral set includes two multichannel buffered serial ports (McBSPs); three 32-bit general-purpose timers; a user-configurable 16-bit or 32-bit host-port interface (HPI16/HPI32); a peripheral component interconnect (PCI); a general-purpose input/output port (GPIO) with 16 GPIO pins; and a glueless external memory interface (32-bit EMIF), which is capable of interfacing to synchronous and asynchronous memories and peripherals.

The C6411 has a complete set of development tools which includes: a new C compiler, an assembly optimizer to simplify programming and scheduling, and a Windows™ debugger interface for visibility into source code execution.



SPRS196 - MARCH 2002

device characteristics

Table 1 provides an overview of the C6411 DSP. The table shows significant features of the C6411 device, including the capacity of on-chip RAM, the peripherals, the CPU frequency, and the package type with pin count.

Table 1. Characteristics of the C6411 Processor

	HARDWARE FEATURES	C6411
	EMIF (32-bit bus width)	1
	EDMA (64 independent channels)	1
	HPI (32- or 16-bit user selectable)	1 (HPI16 or HPI32)
Peripherals	PCI (32-bit)	1
	McBSPs (McBSP0 and McBSP1)	2
	32-Bit Timers	3
	General-Purpose Input/Outputs (GPIOs)	16
	Size (Bytes)	288K
On-Chip Memory	Organization	16K-Byte (16KB) L1 Program (L1P) Cache 16KB L1 Data (L1D) Cache 256KB Unified Mapped RAM/Cache (L2)
CPU ID + CPU Rev ID	Control Status Register (CSR.[31:16])	0x0C01
Frequency	MHz	300
Cycle Time	ns	3.3 ns (C6411-300)
	Core (V)	1 V (-300)
Voltage	I/O (V)	3.3 V
PLL Options	CLKIN frequency multiplier	Bypass (x1), x6
BGA Package	23 x 23 mm	532-Pin BGA (GLZ)
Process Technology	μm	0.12 μm
Product Status†	Product Preview (PP) Advance Information (AI) Production Data (PD)	PP
Device Part Numbers	(For more details on the C6000™ DSP part numbering, see Figure 4)	TMX320C6411GLZ

[†] PRODUCT PREVIEW information concerns products in the formative or design phase of development. Characteristic data and other specifications are design goals. Texas Instruments reserves the right to change or discontinue these products without notice. ADVANCE INFORMATION concerns new products in the sampling or preproduction phase of development. Characteristic data and other specifications are subject to change without notice.

PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.



device compatibility

The C64x[™] family of devices has a diverse and powerful set of peripherals. The common peripheral set that the C6411, C6414, C6415, and C6416 devices offer lead to easier system designs and faster time to market. Table 2 identifies the peripherals and coprocessors that are available on the C6414, C6415, and C6416 devices.

The C6411 device is a low-cost C64x device which features significant enhancements from the C6211/C6211B devices and can be considered a subset of the C6415 device. Table 2 identifies the C6411 features in comparison with the C6211 and C6415 devices.

Table 2. C6211, C6411, and C6415 Device Comparison[†]

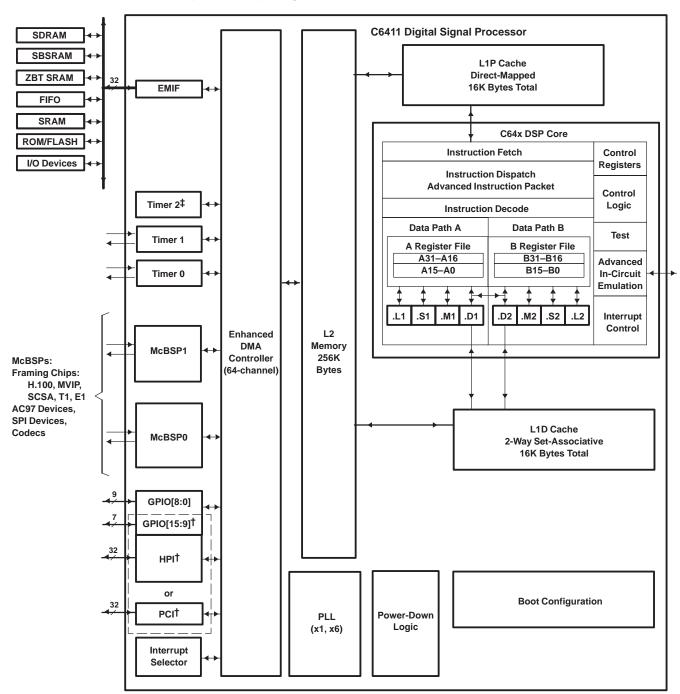
CPU/PERIPHERALS	C6211/C6211B	C6411	C6415
DSP Core	C62x	C64x	C64x
L1P (Program Cache)	4 KB	16 KB	16 KB
L1D (Data Cache)	4 KB	16 KB	16 KB
L2 (Unified Mapped RAM/Cache)	64 KB	256 KB	1024 KB
EMIF (64-, 32-, 16-bit bus width)	(1) 32-Bit	(1) 32-Bit programmable synchronous mode	(1) 64-Bit(1) [EMIFA] (1) 16-Bit [EMIFB] programmable synchronous mode
EDMA (# of independent channels)	16	64	64
HPI (32- or 16-bit user selectable)	16-Bit	32-/16-Bit	32-/16-Bit
PCI (32-bit)	_	32-Bit, 33 MHz	32-Bit, 33 MHz
McBSPs (McBSP0, McBSP1, and McBSP2)	2	2 Enhanced	3 Enhanced
UTOPIA	_	_	(1) Transmit (1) Receive
Timers (32-bit) [TIMER0, TIMER1, TIMER2]	2	3 (No TIMER2 pins)	3
GPIOs (GP[15:0])	_	16	16
Core Frequency (MHz)	150-, 167-MHz	300-MHz	400-, 500-, 600-MHz
Core Voltage (V)	1.8 V	1 V	1.2 V to 1.4 V
PLL Modes (x1 [Bypass], x4, x6, x12)	x1, x4	x1, x6	x1, x6, x12
Package	256-pin BGA 27 x 27 mm GFN suffix	532-pin BGA 23 x 23 mm GLZ suffix	532-pin BGA 23 x 23 mm GLZ suffix
Process Technology	0.18 μm	0.12 μm	0.12 μm

^{†—} denotes peripheral/coprocessor is *not* available on this device.

For more detailed information on the device compatibility and similarities/differences among the C6211, C6411, C6414, C6415, and C6416 devices, see the *How To Begin Development Today With the TMS320C6414, TMS320C6415, and TMS320C6416 DSPs* application report (literature number SPRA718) and *How To Begin Development Today With the TMS320C6411 DSP* application report (literature number SPRA374).



functional block and CPU (DSP core) diagram



[†]The PCI peripheral is muxed with the HPI peripheral and the GPIO[15:9] port. For more details on the multiplexed pins of these peripherals, see the Device Configurations section of this data sheet.

[‡]Timer2 exists internally and is *not* pinned out externally.

SPRS196 - MARCH 2002

CPU (DSP core) description

The CPU fetches VelociTI™ advanced very-long instruction words (VLIWs) (256 bits wide) to supply up to eight 32-bit instructions to the eight functional units during every clock cycle. The VelociTI™ VLIW architecture features controls by which all eight units do not have to be supplied with instructions if they are not ready to execute. The first bit of every 32-bit instruction determines if the next instruction belongs to the same execute packet as the previous instruction, or whether it should be executed in the following clock as a part of the next execute packet. Fetch packets are always 256 bits wide; however, the execute packets can vary in size. The variable-length execute packets are a key memory-saving feature, distinguishing the C64x CPUs from other VLIW architectures. The C64x™ VelociTI.2™ extensions add enhancements to the TMS320C62x™ DSP VelociTI™ architecture. These enhancements include:

- Register file enhancements
- Data path extensions
- Quad 8-bit and dual 16-bit extensions with data flow enhancements
- Additional functional unit hardware
- Increased orthogonality of the instruction set
- Additional instructions that reduce code size and increase register flexibility

The CPU features two sets of functional units. Each set contains four units and a register file. One set contains functional units .L1, .S1, .M1, and .D1; the other set contains units .D2, .M2, .S2, and .L2. The two register files each contain 32 32-bit registers for a total of 64 general-purpose registers. In addition to supporting the packed 16-bit and 32-/40-bit fixed-point data types found in the C62x™ VelociTl™ VLIW architecture, the C64x™ register files also support packed 8-bit data and 64-bit fixed-point data types. The two sets of functional units, along with two register files, compose sides A and B of the CPU [see the functional block and CPU (DSP core) diagram, and Figure 1]. The four functional units on each side of the CPU can freely share the 32 registers belonging to that side. Additionally, each side features a "data cross path"—a single data bus connected to all the registers on the other side, by which the two sets of functional units can access data from the register files on the opposite side. The C64x CPU pipelines data-cross-path accesses over multiple clock cycles. This allows the same register to be used as a data-cross-path operand by multiple functional units in the same execute packet. All functional units in the C64x CPU can access operands via the data cross path. Register access by functional units on the same side of the CPU as the register file can service all the units in a single clock cycle. On the C64x CPU, a delay clock is introduced whenever an instruction attempts to read a register via a data cross path if that register was updated in the previous clock cycle.

In addition to the C62xTM DSP fixed-point instructions, the C64xTM DSP includes a comprehensive collection of quad 8-bit and dual 16-bit instruction set extensions. These VelociTI.2TM extensions allow the C64x CPU to operate directly on packed data to streamline data flow and increase instruction set efficiency.

Another key feature of the C64x CPU is the load/store architecture, where all instructions operate on registers (as opposed to data in memory). Two sets of data-addressing units (.D1 and .D2) are responsible for all data transfers between the register files and the memory. The data address driven by the .D units allows data addresses generated from one register file to be used to load or store data to or from the other register file. The C64x .D units can load and store bytes (8 bits), half-words (16 bits), and words (32 bits) with a single instruction. And with the new data path extensions, the C64x .D unit can load and store doublewords (64 bits) with a single instruction. Furthermore, the non-aligned load and store instructions allow the .D units to access words and doublewords on any byte boundary. The C64x CPU supports a variety of indirect addressing modes using either linear- or circular-addressing with 5- or 15-bit offsets. All instructions are conditional, and most can access any one of the 64 registers. Some registers, however, are singled out to support specific addressing modes or to hold the condition for conditional instructions (if the condition is not automatically "true").



SPRS196 - MARCH 2002

CPU (DSP core) description (continued)

The two .M functional units perform all multiplication operations. Each of the C64x .M units can perform two 16×16 -bit multiplies or four 8×8 -bit multiplies per clock cycle. The .M unit can also perform 16×32 -bit multiplies operations, dual 16×16 -bit multiplies with add/subtract operations, and quad 8×8 -bit multiplies with add operations. In addition to standard multiplies, the C64x .M units include bit-count, rotate, Galois field multiplies, and bidirectional variable shift hardware.

The two .S and .L functional units perform a general set of arithmetic, logical, and branch functions with results available every clock cycle. The arithmetic and logical functions on the C64x CPU include single 32-bit, dual 16-bit, and quad 8-bit operations.

The processing flow begins when a 256-bit-wide instruction fetch packet is fetched from a program memory. The 32-bit instructions destined for the individual functional units are "linked" together by "1" bits in the least significant bit (LSB) position of the instructions. The instructions that are "chained" together for simultaneous execution (up to eight in total) compose an execute packet. A "0" in the LSB of an instruction breaks the chain, effectively placing the instructions that follow it in the next execute packet. A C64x™ DSP device enhancement now allows execute packets to cross fetch-packet boundaries. In the TMS320C62x™/TMS320C67x™ DSP devices, if an execute packet crosses the fetch-packet boundary (256 bits wide), the assembler places it in the next fetch packet, while the remainder of the current fetch packet is padded with NOP instructions. In the C64x™ DSP device, the execute boundary restrictions have been removed, thereby, eliminating all of the NOPs added to pad the fetch packet, and thus, decreasing the overall code size. The number of execute packets within a fetch packet can vary from one to eight. Execute packets are dispatched to their respective functional units at the rate of one per clock cycle and the next 256-bit fetch packet is not fetched until all the execute packets from the current fetch packet have been dispatched. After decoding, the instructions simultaneously drive all active functional units for a maximum execution rate of eight instructions every clock cycle. While most results are stored in 32-bit registers, they can be subsequently moved to memory as bytes, half-words, or doublewords. All load and store instructions are byte-, half-word-, word-, or doubleword-addressable.

For more details on the C64x CPU functional units enhancements, see the following documents:

The TMS320C6000 CPU and Instruction Set Reference Guide (literature number SPRU189)

TMS320C64x Technical Overview (literature number SPRU395)

How To Begin Development Today With the TMS320C6411 DSP application report (literature number SPRA374)



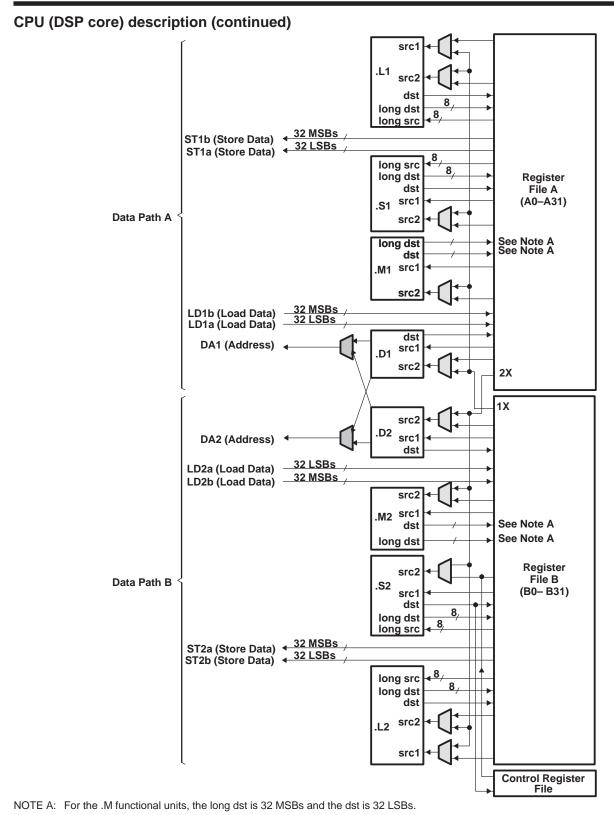


Figure 1. TMS320C64x™ CPU (DSP Core) Data Paths



SPRS196 - MARCH 2002

memory map summary

Table 3 shows the memory map address ranges of the C6411 device. Internal memory is always located at address 0 and can be used as both program and data memory. The external memory address range in the C6411 device begins at the hex address location 0x8000 0000 for the EMIF.

Table 3. TMS320C6411 Memory Map Summary

MEMORY BLOCK DESCRIPTION	BLOCK SIZE (BYTES)	HEX ADDRESS RANGE
Internal RAM (L2)	256K	0000 0000 - 0003 FFFF
Reserved	24M – 256K	0004 0000 - 017F FFFF
External Memory Interface (EMIF) Registers	256K	0180 0000 - 0183 FFFF
L2 Registers	256K	0184 0000 - 0187 FFFF
HPI Registers	256K	0188 0000 - 018B FFFF
McBSP 0 Registers	256K	018C 0000 - 018F FFFF
McBSP 1 Registers	256K	0190 0000 - 0193 FFFF
Timer 0 Registers	256K	0194 0000 - 0197 FFFF
Timer 1 Registers	256K	0198 0000 - 019B FFFF
Interrupt Selector Registers	256K	019C 0000 - 019F FFFF
EDMA RAM and EDMA Registers	256K	01A0 0000 - 01A3 FFFF
Reserved	512K	01A4 0000 - 01AB FFFF
Timer 2 Registers	256K	01AC 0000 - 01AF FFFF
GPIO Registers	256K	01B0 0000 - 01B3 FFFF
Reserved	768K	01B4 0000 - 01BF FFFF
PCI Registers	256K	01C0 0000 - 01C3 FFFF
Reserved	4M – 256K	01C4 0000 - 01FF FFFF
QDMA Registers	52	0200 0000 - 0200 0033
Reserved	736M – 52	0200 0034 - 2FFF FFFF
McBSP 0 Data	64M	3000 0000 - 33FF FFFF
McBSP 1 Data	64M	3400 0000 - 37FF FFFF
Reserved	1G + 128M	3800 0000 - 7FFF FFFF
EMIF CEO [†]	256M	8000 0000 - 8FFF FFFF
EMIF CE1 [†]	256M	9000 0000 - 9FFF FFFF
EMIF CE2 [†]	256M	A000 0000 - AFFF FFFF
EMIF CE3 [†]	256M	B000 0000 - BFFF FFFF
Reserved	1G	C000 0000 - FFFF FFFF

[†] The number of EMIF address pins (EA[21:2]) limits the maximum addressable memory (SDRAM) to 128MB per CE space. To get 256MB of addressable memory, an additional general-purpose output pin or external logic is required.



peripheral register descriptions

Table 4 through Table 18 identify the peripheral registers for the C6411 device by their register names, acronyms, and hex address or hex address range. For more detailed information on the register contents, bit names and their descriptions, see the *TMS320C6000 Peripherals Reference Guide* (literature number SPRU190).

Table 4. EMIF Registers

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME
0180 0000	GBLCTL	EMIF global control
0180 0004	CECTL1	EMIF CE1 space control
0180 0008	CECTL0	EMIF CE0 space control
0180 000C	-	Reserved
0180 0010	CECTL2	EMIF CE2 space control
0180 0014	CECTL3	EMIF CE3 space control
0180 0018	SDCTL	EMIF SDRAM control
0180 001C	SDTIM	EMIF SDRAM refresh control
0180 0020	SDEXT	EMIF SDRAM extension
0180 0024 - 0180 0040	-	Reserved
0180 0044	CESEC1	EMIF CE1 space secondary control
0180 0048	CESEC0	EMIF CE0 space secondary control
0180 004C	-	Reserved
0180 0050	CESEC2	EMIF CE2 space secondary control
0180 0054	CESEC3	EMIF CE3 space secondary control
0180 0058 – 0183 FFFF	-	Reserved

peripheral register descriptions (continued)

Table 5. L2 Cache Registers

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME	COMMENTS
0184 0000	CCFG	Cache configuration register	
	-	Reserved	
0184 2000	L2ALLOC0	L2 allocation register 0	
0184 2004	L2ALLOC1	L2 allocation register 1	
0184 2008	L2ALLOC2	L2 allocation register 2	
0184 200C	L2ALLOC3	L2 allocation register 3	
	_	Reserved	
0184 4000	L2FBAR	L2 flush base address register	
0184 4004	L2FWC	L2 flush word count register	
0184 4010	L2CBAR	L2 clean base address register	
0184 4014	L2CWC	L2 clean word count register	
0184 4020	L1PFBAR	L1P flush base address register	
0184 4024	L1PFWC	L1P flush word count register	
0184 4030	L1DFBAR	L1D flush base address register	
0184 4034	L1DFWC	L1D flush word count register	
	-	Reserved	
0184 5000	L2FLUSH	L2 flush register	
0184 5004	L2CLEAN	L2 clean register	
	-	Reserved	
0184 8000 -0184 81FC	MAR0 to MAR127	Reserved	
0184 8200	MAR128	Controls EMIF CE0 range 8000 0000 – 80FF FFFF	
0184 8204	MAR129	Controls EMIF CE0 range 8100 0000 – 81FF FFFF	
0184 8208	MAR130	Controls EMIF CE0 range 8200 0000 – 82FF FFFF	
0184 820C	MAR131	Controls EMIF CE0 range 8300 0000 – 83FF FFFF	
0184 8210	MAR132	Controls EMIF CE0 range 8400 0000 – 84FF FFFF	
0184 8214	MAR133	Controls EMIF CE0 range 8500 0000 – 85FF FFFF	
0184 8218	MAR134	Controls EMIF CE0 range 8600 0000 – 86FF FFFF	
0184 821C	MAR135	Controls EMIF CE0 range 8700 0000 – 87FF FFFF	
0184 8220	MAR136	Controls EMIF CE0 range 8800 0000 – 88FF FFFF	
0184 8224	MAR137	Controls EMIF CE0 range 8900 0000 – 89FF FFFF	
0184 8228	MAR138	Controls EMIF CE0 range 8A00 0000 – 8AFF FFFF	
0184 822C	MAR139	Controls EMIF CE0 range 8B00 0000 – 8BFF FFFF	
0184 8230	MAR140	Controls EMIF CE0 range 8C00 0000 – 8CFF FFFF	
0184 8234	MAR141	Controls EMIF CE0 range 8D00 0000 – 8DFF FFFF	
0184 8238	MAR142	Controls EMIF CE0 range 8E00 0000 – 8EFF FFFF	
0184 823C	MAR143	Controls EMIF CE0 range 8F00 0000 – 8FFF FFFF	
0184 8240	MAR144	Controls EMIF CE1 range 9000 0000 – 90FF FFFF	
0184 8244	MAR145	Controls EMIF CE1 range 9100 0000 – 91FF FFFF	
0184 8248	MAR146	Controls EMIF CE1 range 9200 0000 – 92FF FFFF	





peripheral register descriptions (continued)

Table 5. L2 Cache Registers (Continued)

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME	COMMENTS
0184 824C	MAR147	Controls EMIF CE1 range 9300 0000 – 93FF FFFF	
0184 8250	MAR148	Controls EMIF CE1 range 9400 0000 – 94FF FFFF	
0184 8254	MAR149	Controls EMIF CE1 range 9500 0000 - 95FF FFFF	
0184 8258	MAR150	Controls EMIF CE1 range 9600 0000 - 96FF FFFF	
0184 825C	MAR151	Controls EMIF CE1 range 9700 0000 – 97FF FFFF	
0184 8260	MAR152	Controls EMIF CE1 range 9800 0000 - 98FF FFFF	
0184 8264	MAR153	Controls EMIF CE1 range 9900 0000 - 99FF FFFF	
0184 8268	MAR154	Controls EMIF CE1 range 9A00 0000 - 9AFF FFFF	
0184 826C	MAR155	Controls EMIF CE1 range 9B00 0000 - 9BFF FFFF	
0184 8270	MAR156	Controls EMIF CE1 range 9C00 0000 - 9CFF FFFF	
0184 8274	MAR157	Controls EMIF CE1 range 9D00 0000 - 9DFF FFFF	
0184 8278	MAR158	Controls EMIF CE1 range 9E00 0000 - 9EFF FFFF	
0184 827C	MAR159	Controls EMIF CE1 range 9F00 0000 - 9FFF FFFF	
0184 8280	MAR160	Controls EMIF CE2 range A000 0000 – A0FF FFFF	
0184 8284	MAR161	Controls EMIF CE2 range A100 0000 - A1FF FFFF	
0184 8288	MAR162	Controls EMIF CE2 range A200 0000 - A2FF FFFF	
0184 828C	MAR163	Controls EMIF CE2 range A300 0000 – A3FF FFFF	
0184 8290	MAR164	Controls EMIF CE2 range A400 0000 – A4FF FFFF	
0184 8294	MAR165	Controls EMIF CE2 range A500 0000 – A5FF FFFF	
0184 8298	MAR166	Controls EMIF CE2 range A600 0000 - A6FF FFFF	
0184 829C	MAR167	Controls EMIF CE2 range A700 0000 – A7FF FFFF	
0184 82A0	MAR168	Controls EMIF CE2 range A800 0000 – A8FF FFFF	
0184 82A4	MAR169	Controls EMIF CE2 range A900 0000 – A9FF FFFF	
0184 82A8	MAR170	Controls EMIF CE2 range AA00 0000 – AAFF FFFF	
0184 82AC	MAR171	Controls EMIF CE2 range AB00 0000 – ABFF FFFF	
0184 82B0	MAR172	Controls EMIF CE2 range AC00 0000 – ACFF FFFF	
0184 82B4	MAR173	Controls EMIF CE2 range AD00 0000 – ADFF FFFF	
0184 82B8	MAR174	Controls EMIF CE2 range AE00 0000 – AEFF FFFF	
0184 82BC	MAR175	Controls EMIF CE2 range AF00 0000 – AFFF FFFF	
0184 82C0	MAR176	Controls EMIF CE3 range B000 0000 – B0FF FFFF	
0184 82C4	MAR177	Controls EMIF CE3 range B100 0000 – B1FF FFFF	
0184 82C8	MAR178	Controls EMIF CE3 range B200 0000 – B2FF FFFF	
0184 82CC	MAR179	Controls EMIF CE3 range B300 0000 – B3FF FFFF	
0184 82D0	MAR180	Controls EMIF CE3 range B400 0000 – B4FF FFFF	
0184 82D4	MAR181	Controls EMIF CE3 range B500 0000 – B5FF FFFF	
0184 82D8	MAR182	Controls EMIF CE3 range B600 0000 – B6FF FFFF	
0184 82DC	MAR183	Controls EMIF CE3 range B700 0000 – B7FF FFFF	
0184 82E0	MAR184	Controls EMIF CE3 range B800 0000 – B8FF FFFF	
0184 82E4	MAR185	Controls EMIF CE3 range B900 0000 – B9FF FFFF	
0184 82E8	MAR186	Controls EMIF CE3 range BA00 0000 – BAFF FFFF	
0184 82EC	MAR187	Controls EMIF CE3 range BB00 0000 – BBFF FFFF	
0184 82F0	MAR188	Controls EMIF CE3 range BC00 0000 – BCFF FFFF	



SPRS196 - MARCH 2002

peripheral register descriptions (continued)

Table 5. L2 Cache Registers (Continued)

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME	COMMENTS
0184 82F4	MAR189	Controls EMIF CE3 range BD00 0000 – BDFF FFFF	
0184 82F8	MAR190	Controls EMIF CE3 range BE00 0000 - BEFF FFFF	
0184 82FC	MAR191	Controls EMIF CE3 range BF00 0000 – BFFF FFFF	
0184 8300 -0184 83FC	MAR192 to MAR255	Reserved	
0184 8400 -0187 FFFF	_	Reserved	

peripheral register descriptions (continued)

Table 6. EDMA Registers

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME
01A0 FF9C	EPRH	Event polarity high register
01A0 FFA4	CIPRH	Channel interrupt pending high register
01A0 FFA8	CIERH	Channel interrupt enable high register
01A0 FFAC	CCERH	Channel chain enable high register
01A0 FFB0	ERH	Event high register
01A0 FFB4	EERH	Event enable high register
01A0 FFB8	ECRH	Event clear high register
01A0 FFBC	ESRH	Event set high register
01A0 FFC0	PQAR0	Priority queue allocation register 0
01A0 FFC4	PQAR1	Priority queue allocation register 1
01A0 FFC8	PQAR2	Priority queue allocation register 2
01A0 FFCC	PQAR3	Priority queue allocation register 3
01A0 FFDC	EPRL	Event polarity low register
01A0 FFE0	PQSR	Priority queue status register
01A0 FFE4	CIPRL	Channel interrupt pending low register
01A0 FFE8	CIERL	Channel interrupt enable low register
01A0 FFEC	CCERL	Channel chain enable low register
01A0 FFF0	ERL	Event low register
01A0 FFF4	EERL	Event enable low register
01A0 FFF8	ECRL	Event clear low register
01A0 FFFC	ESRL	Event set low register
01A1 0000 – 01A3 FFFF	_	Reserved

SPRS196 - MARCH 2002

peripheral register descriptions (continued)

Table 7. EDMA Parameter RAM[†]

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME	COMMENTS
01A0 0000 - 01A0 0017	_	Parameters for Event 0 (6 words)	
01A0 0018 - 01A0 002F	-	Parameters for Event 1 (6 words)	
01A0 0030 - 01A0 0047	-	Parameters for Event 2 (6 words)	
01A0 0048 - 01A0 005F	_	Parameters for Event 3 (6 words)	
01A0 0060 - 01A0 0077	_	Parameters for Event 4 (6 words)	
01A0 0078 - 01A0 008F	-	Parameters for Event 5 (6 words)	
01A0 0090 - 01A0 00A7	_	Parameters for Event 6 (6 words)	
01A0 00A8 - 01A0 00BF	_	Parameters for Event 7 (6 words)	
01A0 00C0 - 01A0 00D7	-	Parameters for Event 8 (6 words)	
01A0 00D8 - 01A0 00EF	-	Parameters for Event 9 (6 words)	
01A0 00F0 - 01A0 00107	_	Parameters for Event 10 (6 words)	
01A0 0108 - 01A0 011F	-	Parameters for Event 11 (6 words)	
01A0 0120 - 01A0 0137	-	Parameters for Event 12 (6 words)	
01A0 0138 - 01A0 014F	_	Parameters for Event 13 (6 words)	
01A0 0150 - 01A0 0167	_	Parameters for Event 14 (6 words)	
01A0 0168 - 01A0 017F	-	Parameters for Event 15 (6 words)	
01A0 0150 - 01A0 0167	_	Parameters for Event 16 (6 words)	
01A0 0168 - 01A0 017F	_	Parameters for Event 17 (6 words)	
01A0 05D0 - 01A0 05E7	_	Parameters for Event 62 (6 words)	
01A0 05E8 - 01A0 05FF	-	Parameters for Event 63 (6 words)	
01A0 0600 - 01A0 0617	_	Reload/link parameters for Event M (6 words)	
01A0 0618 - 01A0 062F	_	Reload/link parameters for Event N (6 words)	
01A0 07E0 - 01A0 07F7	_	Reload/link parameters for Event Z (6 words)	
01A0 07F8 - 01A0 07FF	_	Scratch pad area (2 words)	

[†] The C64x device has twenty-one parameter sets [six (6) words each] that can be used to reload/link EDMA transfers.

Table 8. Quick DMA (QDMA) and Pseudo Registers

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME
0200 0000	QOPT	QDMA options parameter register
0200 0004	QSRC	QDMA source address register
0200 0008	QCNT	QDMA frame count register
0200 000C	QDST	QDMA destination address register
0200 0010	QIDX	QDMA index register
0200 0014 - 0200 001C		Reserved
0200 0020	QSOPT	QDMA pseudo options register
0200 0024	QSSRC	QDMA psuedo source address register
0200 0028	QSCNT	QDMA psuedo frame count register
0200 002C	QSDST	QDMA destination address register
0200 0030	QSIDX	QDMA psuedo index register



peripheral register descriptions (continued)

Table 9. Interrupt Selector Registers

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME	COMMENTS
019C 0000	MUXH	Interrupt multiplexer high	Selects which interrupts drive CPU interrupts 10–15 (INT10–INT15)
019C 0004	MUXL	Interrupt multiplexer low	Selects which interrupts drive CPU interrupts 4–9 (INT04–INT09)
019C 0008	EXTPOL	External interrupt polarity	Sets the polarity of the external interrupts (EXT_INT4–EXT_INT7)
019C 000C - 019C 01FF	-	Reserved	
019C 0200	PDCTL	Peripheral power-down control register (see Table 10)	
019C 0204 - 019F FFFF	_	Reserved	

Table 10. Peripheral Power-Down Control Register

ĺ	HEX ADDRESS RANGE	ACRONYM	REGISTER NAME
	019C 0200	PDCTL	Peripheral power-down control register

Table 11. McBSP 0 Registers

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME	COMMENTS
018C 0000	DRR0	McBSP0 data receive register via Configuration Bus	The CPU and EDMA controller can only read this register; they cannot write to it.
0x3000 0000 – 0x33FF FFFF	DRR0	McBSP0 data receive register via Peripheral Data Bus	
018C 0004	DXR0	McBSP0 data transmit register via Configuration Bus	
0x3000 0000 – 0x33FF FFFF	DXR0	McBSP0 data transmit register via Peripheral Data Bus	
018C 0008	SPCR0	McBSP0 serial port control register	
018C 000C	RCR0	McBSP0 receive control register	
018C 0010	XCR0	McBSP0 transmit control register	
018C 0014	SRGR0	McBSP0 sample rate generator register	
018C 0018	MCR0	McBSP0 multichannel control register	
018C 001C	RCERE00	McBSP0 enhanced receive channel enable register 0	
018C 0020	XCERE00	McBSP0 enhanced transmit channel enable register 0	
018C 0024	PCR0	McBSP0 pin control register	
018C 0028	RCERE10	McBSP0 enhanced receive channel enable register 1	
018C 002C	XCERE10	McBSP0 enhanced transmit channel enable register 1	
018C 0030	RCERE20	McBSP0 enhanced receive channel enable register 2	
018C 0034	XCERE20	McBSP0 enhanced transmit channel enable register 2	
018C 0038	RCERE30	McBSP0 enhanced receive channel enable register 3	
018C 003C	XCERE30	McBSP0 enhanced transmit channel enable register 3	
018C 0040 – 018F FFFF	_	Reserved	

SPRS196 - MARCH 2002

peripheral register descriptions (continued)

Table 12. McBSP 1 Registers

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME	COMMENTS
0190 0000	DRR1	Data receive register via Configuration Bus	The CPU and EDMA controller can only read this register; they cannot write to it.
0x3400 0000 – 0x37FF FFFF	DRR1	McBSP1 data receive register via Peripheral Data Bus	
0190 0004	DXR1	McBSP1 data transmit register via Configuration Bus	
0x3400 0000 – 0x37FF FFFF	DXR1	McBSP1 data transmit register via Peripheral Data Bus	
0190 0008	SPCR1	McBSP1 serial port control register	
0190 000C	RCR1	McBSP1 receive control register	
0190 0010	XCR1	McBSP1 transmit control register	
0190 0014	SRGR1	McBSP1 sample rate generator register	
0190 0018	MCR1	McBSP1 multichannel control register	
0190 001C	RCERE01	McBSP1 enhanced receive channel enable register 0	
0190 0020	XCERE01	McBSP1 enhanced transmit channel enable register 0	
0190 0024	PCR1	McBSP1 pin control register	
0190 0028	RCERE11	McBSP1 enhanced receive channel enable register 1	
0190 002C	XCERE11	McBSP1 enhanced transmit channel enable register 1	
0190 0030	RCERE21	McBSP1 enhanced receive channel enable register 2	
0190 0034	XCERE21	McBSP1 enhanced transmit channel enable register 2	
0190 0038	RCERE31	McBSP1 enhanced receive channel enable register 3	
0190 003C	XCERE31	McBSP1 enhanced transmit channel enable register 3	
0190 0040 – 0193 FFFF	_	Reserved	



peripheral register descriptions (continued)

Table 13. Timer 0 Registers

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME	COMMENTS
0194 0000	CTL0	Timer 0 control register	Determines the operating mode of the timer, monitors the timer status, and controls the function of the TOUT pin.
0194 0004	PRD0	Timer 0 period register	Contains the number of timer input clock cycles to count. This number controls the TSTAT signal frequency.
0194 0008	CNT0	Timer 0 counter register	Contains the current value of the incrementing counter.
0194 000C - 0197 FFFF	_	Reserved	

Table 14. Timer 1 Registers

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME	COMMENTS
0198 0000	CTL1	Timer 1 control register	Determines the operating mode of the timer, monitors the timer status, and controls the function of the TOUT pin.
0198 0004	PRD1	Timer 1 period register	Contains the number of timer input clock cycles to count. This number controls the TSTAT signal frequency.
0198 0008	CNT1	Timer 1 counter register	Contains the current value of the incrementing counter.
0198 000C - 019B FFFF	_	Reserved	

Table 15. Timer 2 Registers

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME	COMMENTS
01AC 0000	CTL2	Timer 2 control register	Determines the operating mode of the timer, monitors the timer status.
01AC 0004	PRD2	Timer 2 period register	Contains the number of timer input clock cycles to count. This number controls the TSTAT signal frequency.
01AC 0008	CNT2	Timer 2 counter register	Contains the current value of the incrementing counter.
01AC 000C - 01AF FFFF	_	Reserved	

SPRS196 - MARCH 2002

peripheral register descriptions (continued)

Table 16. HPI Registers

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME	COMMENTS	
-	HPID	HPI data register	Host read/write access only	
0188 0000	HPIC	HPI control register	HPIC has both Host/CPU read/write access	
0188 0004	HPIA (HPIAW)†	HPI address register (Write)	HPIA has both Host/CPU	
0188 0008		HPI address register (Read)	read/write access	
0188 0001 – 018B FFFF	_	Reserved		

[†] Host access to the HPIA register updates both the HPIAW and HPIAR registers. The CPU can access HPIAW and HPIAR independently.

Table 17. GPIO Registers

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME	
01B0 0000	GPEN	GPIO enable register	
01B0 0004	GPDIR	GPIO direction register	
01B0 0008	GPVAL	GPIO value register	
01B0 000C	_	Reserved	
01B0 0010	GPDH	GPIO delta high register	
01B0 0014	GPHM	GPIO high mask register	
01B0 0018	GPDL	GPIO delta low register	
01B0 001C	GPLM	GPIO low mask register	
01B0 0020	GPGC	GPIO global control register	
01B0 0024	GPPOL	GPIO interrupt polarity register	
01B0 0028 - 01B3 FFFF	_	Reserved	

peripheral register descriptions (continued)

Table 18. PCI Peripheral Registers

HEX ADDRESS RANGE	ACRONYM	REGISTER NAME
01C0 0000	RSTSRC	DSP Reset source/status register
01C0 0004	PMDCSR	Power management DSP control/status register
01C0 0008	PCIIS	PCI interrupt source register
01C0 000C	PCIIEN	PCI interrupt enable register
01C0 0010	DSPMA	DSP master address register
01C0 0014	PCIMA	PCI master address register
01C0 0018	PCIMC	PCI master control register
01C0 001C	CDSPA	Current DSP address register
01C0 0020	CPCIA	Current PCI address register
01C0 0024	CCNT	Current byte count register
01C0 0028	-	Reserved
01C0 002C - 01C1 FFEF	-	Reserved
0x01C1 FFF0	HSR	Host status register
0x01C1 FFF4	HDCR	Host-to-DSP control register
0x01C1 FFF8	DSPP	DSP page register
0x01C1 FFFC	-	Reserved
01C2 0000	EEADD	EEPROM address register
01C2 0004	EEDAT	EEPROM data register
01C2 0008	EECTL	EEPROM control register
01C2 000C - 01C3 FFFF	-	Reserved

SPRS196 - MARCH 2002

EDMA channel synchronization events

The C64x EDMA supports up to 64 EDMA channels which service peripheral devices and external memory. Table 19 lists the source of C64x EDMA synchronization events associated with each of the programmable EDMA channels. For the C6411 device, the association of an event to a channel is fixed; each of the EDMA channels has one specific event associated with it. These specific events are captured in the EDMA event registers (ERL, ERH) even if the events are disabled by the EDMA event enable registers (EERL, EERH). The priority of each event can be specified independently in the transfer parameters stored in the EDMA parameter RAM. For more detailed information on the EDMA module and how EDMA events are enabled, captured, processed, linked, chained, and cleared, etc., see the EDMA Controller chapter of the *TMS320C6000 Peripherals Reference Guide* (literature number SPRU190).

Table 19. TMS320C6411 EDMA Channel Synchronization Events[†]

EDMA CHANNEL	EVENT NAME	EVENT DESCRIPTION			
0	DSP_INT	HPI/PCI-to-DSP interrupt			
1	TINT0	Timer 0 interrupt			
2	TINT1	Timer 1 interrupt			
3	SD_INT	EMIF SDRAM timer interrupt			
4	GPINT4/EXT_INT4	GPIO event 4/External interrupt pin 4			
5	GPINT5/EXT_INT5	GPIO event 5/External interrupt pin 5			
6	GPINT6/EXT_INT6	GPIO event 6/External interrupt pin 6			
7	GPINT7/EXT_INT7	GPIO event 7/External interrupt pin 7			
8	GPINT0	GPIO event 0			
9	GPINT1	GPIO event 1			
10	GPINT2	GPIO event 2			
11	GPINT3	GPIO event 3			
12	XEVT0	McBSP0 transmit event			
13	REVT0	McBSP0 receive event			
14	XEVT1	McBSP1 transmit event			
15	REVT1	McBSP1 receive event			
16–18	-	None			
19	TINT2	Timer 2 interrupt			
20–47	-	None			
48	GPINT8	GPIO event 8			
49	GPINT9	GPIO event 9			
50	GPINT10	GPIO event 10			
51	GPINT11	GPIO event 11			
52	GPINT12	GPIO event 12			
53	GPINT13	GPIO event 13			
54	GPINT14	GPIO event 14			
55	GPINT15	GPIO event 15			
56–63	-	None			

[†] In addition to the events shown in this table, each of the 64 channels can also be synchronized with the transfer completion or alternate transfer completion events. For more detailed information on EDMA event-transfer chaining, see the EDMA Controller chapter of the *TMS320C6000 Peripherals Reference Guide* (literature number SPRU190).



interrupt sources and interrupt selector

The C64x DSP core supports 16 prioritized interrupts, which are listed in Table 20. The highest-priority interrupt is INT_00 (dedicated to RESET) while the lowest-priority interrupt is INT_15. The first four interrupts (INT_00-INT_03) are non-maskable and fixed. The remaining interrupts (INT_04-INT_15) are maskable and default to the interrupt source specified in Table 20. The interrupt source for interrupts 4–15 can be programmed by modifying the selector value (binary value) in the corresponding fields of the Interrupt Selector Control registers: MUXH (address 0x019C0000) and MUXL (address 0x019C0004).

Table 20. C6411 DSP Interrupts

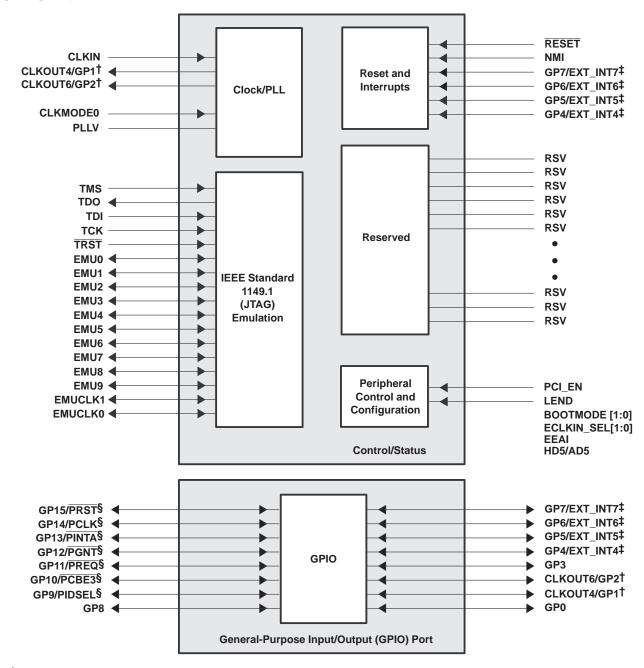
CPU INTERRUPT NUMBER	INTERRUPT SELECTOR CONTROL REGISTER	SELECTOR VALUE (BINARY)	INTERRUPT EVENT	INTERRUPT SOURCE
INT_00 [†]	-	-	RESET	
INT_01 [†]	-	-	NMI	
INT_02†	-	ı	Reserved	Reserved. Do not use.
INT_03†	ı	ı	Reserved	Reserved. Do not use.
INT_04‡	MUXL[4:0]	00100	GPINT4/EXT_INT4	GPIO interrupt 4/External interrupt pin 4
INT_05 [‡]	MUXL[9:5]	00101	GPINT5/EXT_INT5	GPIO interrupt 5/External interrupt pin 5
INT_06 [‡]	MUXL[14:10]	00110	GPINT6/EXT_INT6	GPIO interrupt 6/External interrupt pin 6
INT_07 [‡]	MUXL[20:16]	00111	GPINT7/EXT_INT7	GPIO interrupt 7/External interrupt pin 7
INT_08 [‡]	MUXL[25:21]	01000	EDMA_INT	EDMA channel (0 through 63) interrupt
INT_09 [‡]	MUXL[30:26]	01001	EMU_DTDMA	EMU DTDMA
INT_10 [‡]	MUXH[4:0]	00011	SD_INT	EMIF SDRAM timer interrupt
INT_11 [‡]	MUXH[9:5]	01010	EMU_RTDXRX	EMU real-time data exchange (RTDX) receive
INT_12 [‡]	MUXH[14:10]	01011	EMU_RTDXTX	EMU RTDX transmit
INT_13 [‡]	MUXH[20:16]	00000	DSP_INT	HPI/PCI-to-DSP interrupt
INT_14 [‡]	MUXH[25:21]	00001	TINT0	Timer 0 interrupt
INT_15 [‡]	MUXH[30:26]	00010	TINT1	Timer 1 interrupt
_	-	01100	XINT0	McBSP0 transmit interrupt
_	-	01101	RINT0	McBSP0 receive interrupt
_	-	01110	XINT1	McBSP1 transmit interrupt
_	-	01111	RINT1	McBSP1 receive interrupt
_	-	10000	GPINT0	GPIO interrupt 0
_	_	10001	Reserved	Reserved. Do not use.
_	_	10010	Reserved	Reserved. Do not use.
_	-	10011	TINT2	Timer 2 interrupt
_	_	10100 – 11111	Reserved	Reserved. Do not use.

[†] Interrupts INT_00 through INT_03 are non-maskable and fixed.



[‡] Interrupts INT_04 through INT_15 are programmable by modifying the binary selector values in the Interrupt Selector Control registers fields. Table 20 shows the default interrupt sources for Interrupts INT_04 through INT_15. For more detailed information on interrupt sources and selection, see the Interrupt Selector and External Interrupts chapter of the TMS320C6000 Peripherals Reference Guide (literature number SPRU190).

signal groups description



- † These pins are muxed with the GPIO port pins and by default these signals function as clocks (CLKOUT4 or CLKOUT6). To use these muxed pins as GPIO signals, the appropriate GPIO register bits (GPxEN and GPxDIR) must be properly enabled and configured. For more details, see the Device Configurations section of this data sheet.
- ‡ These pins are GPIO pins that can also function as external interrupt sources (EXT_INT[7:4]). Default after reset is EXT_INTx or GPIO as input-only.
- § These GPIO pins are muxed with the PCI peripheral pins and by default these signals are set up to no function with both the GPIO and PCI pin functions disabled. For more details on these muxed pins, see the Device Configurations section of this data sheet.

Figure 2. CPU and Peripheral Signals



signal groups description (continued)

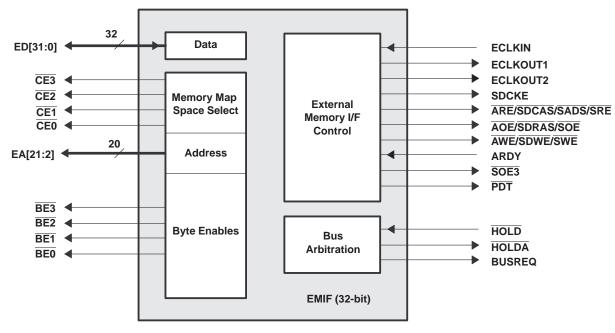
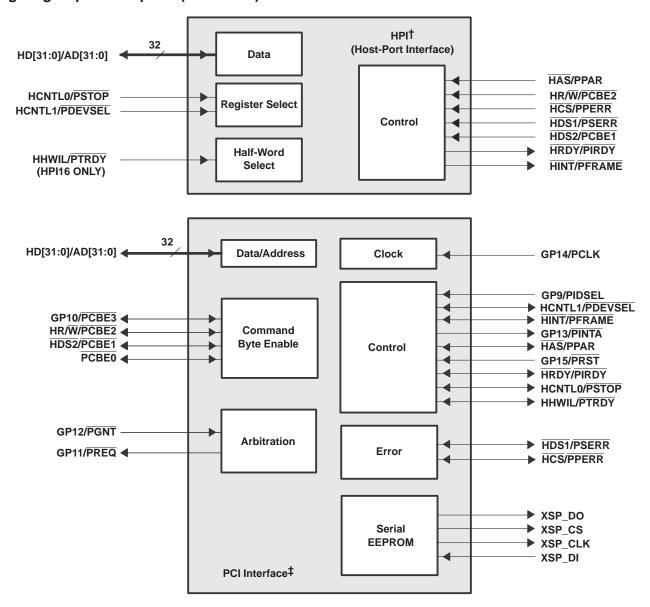


Figure 3. Peripheral Signals

signal groups description (continued)



[†] These HPI pins are muxed with the PCI peripheral. By default, these signals function as HPI. For more details on these muxed pins, see the Device Configurations section of this data sheet.

Figure 3. Peripheral Signals (Continued)



[‡] These PCI pins (excluding PCBEO, XSP_DO, XSP_CLK, XSP_DI, and XSP_CS) are muxed with the HPI or GPIO peripherals. By default, these signals function as HPI and no function, respectively. For more details on these muxed pins, see the Device Configurations section of this data sheet.

signal groups description (continued)

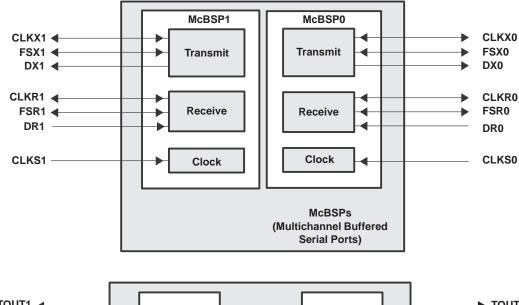




Figure 3. Peripheral Signals (Continued)

SPRS196 - MARCH 2002

DEVICE CONFIGURATIONS

The C6411 peripheral selections and other device configurations are determined by external pullup/pulldown resistors on the following pins (all of which are latched during device reset):

- peripherals selection
 - PCI_EN
- other device configurations
 - LEND
 - BOOTMODE [1:0]
 - ECLKIN_SEL[1:0]
 - EEAI
 - HD5/AD5

peripherals selection

Some C6411 peripherals share the same pins (internally muxed) and are mutually exclusive (i.e., HPI, general-purpose input/output pins GP[15:9], and PCI). Other C6411 peripherals (i.e., EMIF, three Timers, two McBSPs, and the GP[8:0] pins), are always available.

HPI/GP[15:9] versus PCI

The PCI_EN pin is latched at reset. This pin determines the HPI/GP[15:9] versus the PCI peripheral selection, summarized in Table 21.



DEVICE CONFIGURATIONS (CONTINUED)

Table 21. PCI_EN Peripheral Selection (HPI/GP[15:9] or PCI)

DOL EN Divit				PERIPHERALS SELECTED
PCI_EN Pin†	HPI	GP[15:9]	PCI	DESCRIPTION
				[default] HPI is enabled, GP[15:9] pins can be programmed as GPIO, PCI is disabled.
0	V	V		This means all multiplexed HPI/PCI pins function as HPI and all standalone PCI pins (PCBEO, XSP_DO, XSP_DI, XSP_CLK, and XSP_CS) are tied-off (Hi-Z). Also, the multiplexed GPIO/PCI pins can be used as GPIO with the proper software configuration of the GPIO enable (GPxEN) and direction (GPxDIR) registers (for more details, see Table 23).
1			√	PCI is enabled, HPI/GP[15:9] are disabled. This means all multiplexed HPI/PCI pins function as PCI. Also, the multiplexed GPIO/PCI pins function as PCI pins (for more details, see Table 23).
				Auto-initialization through PCI EEPROM or initialization via specified PCI default values is controlled by the EEAI pin, see Table 22.

[†] The PCI_EN pin is latched at reset and *must* be driven valid at all times and the user *must not* switch values throughout device operation.

other device configurations

Table 22 describes the C6411 device configuration pins, which are set up via external pullup/pulldown resistors through the specified pins. For more details on these device configuration pins, see the Terminal Functions table and the Debugging Considerations section.



SPRS196 - MARCH 2002

DEVICE CONFIGURATIONS (CONTINUED)

Table 22. Device Configuration Pins (LEND, BOOTMODE[1:0], ECLKIN_SEL[1:0], EEAI, and HD5/AD5)

CONFIGURATION PIN	NO.	FUNCTIONAL DESCRIPTION			
LEND		Device Endian mode (LEND) 0 - System operates in Big Endian mode 1 - System operates in Little Endian mode (default)			
BOOTMODE[1:0]		Bootmode [1:0]. Default is reserved. External pullup and/or pulldown resistors must be used to select a valid bootmode configuration. 00 - No boot 01 - HPI boot 10 - Reserved (default mode) 11 - EMIF 8-bit ROM boot with default timings			
ECLKIN_SEL[1:0]		EMIF input clock select Clock mode select for EMIF (ECLKIN_SEL[1:0]) 00 - ECLKIN (default mode) 01 - CPU/4 Clock Rate 10 - CPU/6 Clock Rate 11 - Reserved			
EEAI		PCI EEPROM Auto-Initialization (EEAI) PCI auto-initialization via external EEPROM 0 - PCI auto-initialization through EEPROM is disabled; the PCI peripheral uses the specified PCI default values (default). 1 - PCI auto-initialization through EEPROM is enabled; the PCI peripheral is configured through EEPROM provided the PCI peripheral pin is enabled (PCI_EN = 1). Note: If the PCI peripheral is disabled (PCI_EN pin = 0), this pin must not be pulled up. For more information on the PCI EEPROM default values, see the PCI chapter of the TMS320C6000 Peripherals Reference Guide (literature number SPRU190).			
HD5/AD5		HPI configuration bus width (HPI_WIDTH) 0 - HPI operates as an HPI16. (HPI bus is 16 bits wide. HD[15:0] pins are used and the remaining HD[31:16] pins are reserved pins in the Hi-Z state.) 1 - HPI operates as an HPI32. (HPI bus is 32 bits wide. All HD[31:0] pins are used for host-port operations.)			



DEVICE CONFIGURATIONS (CONTINUED)

multiplexed pins

Multiplexed pins are pins that are shared by more than one peripheral and are internally multiplexed. Some of these pins are configured by software, and the others are configured by external pullup/pulldown resistors only at reset. Those muxed pins that are configured by software can be programmed to switch functionalities at any time. Those muxed pins that are configured by external pullup/pulldown resistors are mutually exclusive; only one peripheral has primary control of the function of these pins after reset. Table 23 identifies the multiplexed pins on the C6411 device; shows the default (primary) function and the default settings after reset; and describes the pins, registers, etc. necessary to configure specific multiplexed functions.

debugging considerations

It is recommended that external connections be provided to device configuration pins, including CLKMODE0, LEND, BOOTMODE[1:0], ECLKIN_SEL[1:0]. EEAI, HD5/AD5, and PCI_EN. Although internal pullup/pulldown resistors exist on these pins, providing external connectivity adds convenience to the user in debugging and flexibility in switching operating modes.

Internal pullup/pulldown resistors also exist on specified reserved (RSV) pins. Do not oppose the internal pullup/pulldown resistors, unless otherwised noted, on these RSV pins.

For the internal pullup/pulldown resistors for all device pins, see the terminal functions table.



SPRS196 - MARCH 2002

DEVICE CONFIGURATIONS (CONTINUED)

Table 23. C6411 Device Multiplexed Pins[†]

MULTIPLEXED PINS	DEFAULT FUNCTION	DEFAULT OF THE	DESCRIPTION	
NAME NO.	DEFAULT FUNCTION	DEFAULT SETTING	DESCRIPTION	
CLKOUT4/GP1	CLKOUT4	GP1EN = 0 (disabled)	These pins are software-configurable To use these pins as GPIO pins, the GPxEN bits in the GPIO Enable Register and the GPxDIR bits in the GPIO Direction Register must be	
CLKOUT6/GP2	CLKOUT6	GP2EN = 0 (disabled)	properly configured. GPxEN = 1: GPx pin enabled GPxDIR = 0: GPx pin is an input GPxDIR = 1: GPx pin is an output	
GP9/PIDSEL			To use GP[15:9] as GPIO pins, the PCI	
GP10/PCBE3			needs to be disabled (PCI_EN = 0), the GPxEN bits in the GPIO Enable	
GP11/PREQ		GPxEN = 0 (disabled) PCI_EN = 0 (disabled)†	Register and the GPXDIR bits in the GPIO Direction Register must be properly configured. GPxEN = 1: GPx pin enabled	
GP12/PGNT	None			
GP13/PINTA				
GP14/PCLK			GPxDIR = 0: GPx pin enabled GPxDIR = 0: GPx pin is an input	
GP15/PRST			GPxDIR = 1: GPx pin is an output	
HD[31:0]/AD[31:0] ‡	HD[31:0]			
HAS/PPAR	HAS			
HCNTL1/PDEVSEL	HCNTL1]		
HCNTL0/PSTOP	HCNTL0		By default, HPI is enabled upon reset (PCI is disabled). To enable the PCI peripheral an external pullup resistor (1 $k\Omega$) must be provided on the PCI_EN pin (setting PCI_EN = 1	
HDS1/PSERR	HDS1	PCI_EN = 0 (disabled) [†]		
HDS2/PCBE1	HDS2			
HR/W/PCBE2	HR/W			
HWWIL/PTRDY	HHWIL (HPI16 only)]	at reset and keeping valid "1" after reset).	
HINT/PFRAME	HINT]	ĺ	
HCS/PPERR	HCS	1		
HRDY/PIRDY	HRDY	1		

[†] All other standalone PCI pins are tied-off internally (pins in Hi-Z) when the peripheral is disabled [PCI_EN = 0].



[‡] For the HD[31:0]/AD[31:0] multiplexed pins pin numbers, see the *Terminal Functions* table.

SPRS196 - MARCH 2002

Terminal Functions

SIGNAL NAME NO.	TYPET	IPD/ IPU‡	DESCRIPTION		
CLOCK/PLL CONFIGURATION					
CLKIN	1	IPD	Clock Input. This clock is the input to the on-chip PLL.		
CLKOUT4/GP1§	I/O/Z	IPD	Clock output at 1/4 of the device speed (O/Z) [default] or this pin can be programmed as a GPIO 1 pin (I/O/Z).		
CLKOUT6/GP2§	I/O/Z	IPD	Clock output at 1/6 of the device speed (O/Z) [default] or this pin can be programmed as a GPIO 2 pin (I/O/Z).		
CLKMODE0 I		IPD	Clock mode select Selects whether the CPU clock frequency = input clock frequency x1 (Bypass) [default x6. For more details on the CLKMODE0 pin and the PLL multiply factors, see the Clock section of this data sheet.		
PLLV¶	Α#		PLL voltage supply		
JTAG EMULATION					
TMS	I	IPU	JTAG test-port mode select		
TDO	O/Z	IPU	JTAG test-port data out		
TDI	1	IPU	JTAG test-port data in		
TCK	I	IPU	JTAG test-port clock		
TRST	TRST		JTAG test-port reset		
EMU9	I/O/Z	IPU	Emulation pin 9. Reserved for future use, leave unconnected.		
EMU8	I/O/Z	IPU	Emulation pin 8. Reserved for future use, leave unconnected.		
EMU7	I/O/Z	IPU	Emulation pin 7. Reserved for future use, leave unconnected.		
EMU6	I/O/Z	IPU	Emulation pin 6. Reserved for future use, leave unconnected.		
EMU5	I/O/Z	IPU	Emulation pin 5. Reserved for future use, leave unconnected.		
EMU4	I/O/Z	IPU	Emulation pin 4. Reserved for future use, leave unconnected.		
EMU3	I/O/Z	IPU	Emulation pin 3. Reserved for future use, leave unconnected.		
EMU2	I/O/Z	IPU	Emulation pin 2. Reserved for future use, leave unconnected.		
EMU1	I/O/Z	IPU	Emulation pin 1		
EMU0	I/O/Z	IPU	Emulation pin 0		
EMUCLK1	I/O/Z	IPU	Emulation clock 1. Reserved for future use, leave unconnected.		
EMUCLK0 I/O/Z		IPU	Emulation clock 0. Reserved for future use, leave unconnected.		
LITTLE/BIG ENDIAN FORMAT					
LEND	I/O/Z	IPU	Device Endian mode LEND: 0 - Big Endian 1 - Little Endian (default mode)		

TI = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



[‡] IPD = Internal pulldown, IPU = Internal pullup. (These IPD/IPU signal pins feature a 30-k Ω IPD or IPU resistor. To pull up a signal to the opposite supply rail, a 1-k Ω resistor should be used, unless otherwise noted.)

[§] These pins are multiplexed pins. For more details, see the Device Configurations section of this data sheet.

[¶]PLLV is not part of external voltage supply. See the Clock PLL section for information on how to connect this pin.

[#] A = Analog signal (PLL Filter)

Il The EMU0 and EMU1 pins are internally pulled up with 30-k Ω resistors; therefore, for emulation and normal operation, no external pullup/pulldown resistors are necessary. However, for boundary scan operation, pull down the EMU1 and EMU0 pins with a dedicated 1-k Ω resistor.

SPRS196 - MARCH 2002

Terminal Functions (Continued)

SIGNAL	1		IDD/	·		
NAME	NO.	TYPE†	IPD/ IPU‡	DESCRIPTION		
BOOTMODE						
BOOTMODE1			IPU	Boot mode. Default is reserved. External pullup and/or pulldown resistors must be used to select a valid bootmode configuration.		
BOOTMODE0		I/O/Z	IPD	BOOTMODE[1:0]: 00 - No boot 01 - HPI boot 10 - Reserved (default mode) 11 - EMIF 8-bit ROM boot with default timings		
	RESETS, INTERRUPTS, AND GENERAL-PURPOSE INPUT/OUTPUTS					
RESET		I		Device reset		
NMI	Ì	I	IPD	Nonmaskable interrupt, edge-driven (rising edge)		
GP7/EXT_INT7				General-purpose input/output (GPIO) pins (I/O/Z) or external interrupts (input only). The default after reset setting is GPIO enabled as input-only.		
GP6/EXT_INT6						
GP5/EXT_INT5		I/O/Z	IPU	When these pins function as External Interrupts [by selecting the corresponding interrupt enable register bit (IER.[7:4])], they are edge-driven and the polarity can be independently		
GP4/EXT_INT4				selected via the External Interrupt Polarity Register bits (EXTPOL.[3:0]).		
GP15/PRST§	Ì			General-purpose input/output (GPIO) 15 pin (I/O/Z) or PCI reset (I). No function at default.		
GP14/PCLK§		1 !		GPIO 14 pin (I/O/Z) or PCI clock (I). No function at default.		
GP13/PINTA§				GPIO 13 pin (I/O/Z) or PCI interrupt A (O/Z). No function at default.		
GP12/PGNT§				GPIO 12 pin (I/O/Z) or PCI bus grant (I). No function at default.		
GP11/PREQ§				GPIO 11 pin (I/O/Z) or PCI bus request (O/Z). No function at default.		
GP10/PCBE3§		I/O/Z		GPIO 10 pin (I/O/Z) or PCI command/byte enable 3 (I/O/Z). No function at default.		
GP9/PIDSEL§				GPIO 9 pin (I/O/Z) or PCI initialization device select (I). No function at default.		
GP3			IPD	GPIO 3 pin (I/O/Z).		
GP0			IPD	GPIO 0 pin. The general-purpose I/O 0 pin (GPIO 0) (I/O/Z) can be programmed as GPIO 0 (input only) [default] or as GPIO 0 (output only) pin or output as a general-purpose interrupt (GP0INT) signal (output only).		
GP8		I/O/Z	IPD	This pin has no function at default [default] or this pin can be programmed as a GPIO 8 pin (I/O/Z).		
CLKOUT6/GP2§		I/O/Z	IPD	Clock output at 1/6 of the device speed (O/Z) [default] or this pin can be programmed as a GPIO 2 pin (I/O/Z).		
CLKOUT4/GP1§		I/O/Z	IPD	Clock output at 1/4 of the device speed (O/Z) [default] or this pin can be programmed as a GPIO 1 pin (I/O/Z).		
	HOST-PORT INTERFACE (HPI) or PERIPHERAL COMPONENT INTERCONNECT (PCI)					
PCI_EN		I	IPD	PCI enable pin. This pin controls the selection (enable/disable) of the HPI and GP[15:9], or PCI peripherals. For more details, see the Device Configurations section of this data sheet.		
EEAI		I/O/Z	IPD	PCI EEPROM Auto-Initialization (EEAI) via external EEPROM If the PCI peripheral is disabled (PCI_EN pin = 0), this pin must not be pulled up. EEAI: 0 — PCI auto-initialization through EEPROM is disabled (default). 1 — PCI auto-initialization through EEPROM is enabled.		

[†] I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



[‡] IPD = Internal pulldown, IPU = Internal pullup. (These IPD/IPU signal pins feature a 30-kΩ IPD or IPU resistor. To pull up a signal to the opposite supply rail, a 1-kΩ resistor should be used, unless otherwise noted.)

[§] These pins are multiplexed pins. For more details, see the Device Configurations section of this data sheet.

SPRS196 - MARCH 2002

Terminal Functions (Continued)

SIGNAL			Terminal Functions (Continued)
NAME NO.	TYPET	IPD/ IPU‡	DESCRIPTION
	<u> </u>		I I) or PERIPHERAL COMPONENT INTERCONNECT (PCI) (CONTINUED)
HINT/		7.02 (
PFRAME§	I/O/Z		Host interrupt from DSP to host (0) [default] or PCI frame (I/O/Z)
HCNTL1/ PDEVSEL§	I/O/Z		Host control – selects between control, address, or data registers (I) [default] or PCI device select (I/O/Z).
HCNTL0/ PSTOP§	I/O/Z		Host control – selects between control, address, or data registers (I) [default] or PCI stop (I/O/Z)
HHWIL/ PTRDY§	I/O/Z		Host half-word select – first or second half-word (not necessarily high or low order) [For HPI16 bus width selection only] (I) [default] or PCI target ready (I/O/Z)
HR/W/PCBE2§	I/O/Z		Host read or write select (I) [default] or PCI command/byte enable 2 (I/O/Z)
HAS/PPAR§	I/O/Z		Host address strobe (I) [default] or PCI parity (I/O/Z)
HCS/PPERR§	I/O/Z		Host chip select (I) [default] or PCI parity error (I/O/Z)
HDS1/PSERR§	I/O/Z		Host data strobe 1 (I) [default] or PCI system error (I/O/Z)
HDS2/PCBE1§	I/O/Z		Host data strobe 2 (I) [default] or PCI command/byte enable 1 (I/O/Z)
HRDY/PIRDY§	I/O/Z		Host ready from DSP to host (O) [default] or PCI initiator ready (I/O/Z).
HD31/AD31§			
HD30/AD30§	7		
HD29/AD29§			
HD28/AD28§			
HD27/AD27§			
HD26/AD26§			
HD25/AD25§			Host-port data (I/O/Z) [default] or PCI data-address bus (I/O/Z) As HPI data bus (PCI_EN pin = 0) Used for transfer of data, address, and control
HD24/AD24§	7		
HD23/AD23§			
HD22/AD22§	7		Host-Port bus width user-configurable at device reset via a 10-kΩ resistor pullup/pulldown
HD21/AD21§			resistor on the HD5 pin:
HD20/AD20§	-		HD5 pin = 0: HPI operates as an HPI16.
HD19/AD19§	I/O/Z		(HPI bus is 16 bits wide. HD[15:0] pins are used and the remaining HD[31:16] pins are
HD18/AD18§	7		reserved pins in the high-impedance state.)
HD17/AD17§	7		HD5 pin = 1: HPI operates as an HPI32.
HD16/AD16§			(HPI bus is 32 bits wide. All HD[31:0] pins are used for host-port operations.)
HD15/AD15§			As PCI data-address bus (PCI_EN pin = 1)
HD14/AD14§			Used for transfer of data and address
HD13/AD13§			
HD12/AD12§			
HD11/AD11§			
HD10/AD10§			
HD9/AD9§			
HD8/AD8§			

[†] I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



[‡] IPD = Internal pulldown, IPU = Internal pullup. (These IPD/IPU signal pins feature a 30-k Ω IPD or IPU resistor. To pull up a signal to the opposite supply rail, a 1-k Ω resistor should be used, unless otherwise noted.)

[§] These pins are multiplexed pins. For more details, see the Device Configurations section of this data sheet.

SPRS196 - MARCH 2002

Terminal Functions (Continued)

SIGNAL	IPD/					
NAME NO.	TYPET	IPU‡	DESCRIPTION			
HOST-PORT INTERFACE (HPI) or PERIPHERAL COMPONENT INTERCONNECT (PCI) (CONTINUED)						
HD7/AD7§			Host-port data (I/O/Z) [default] or PCI data-address bus (I/O/Z)			
HD6/AD6§	1	l	As HPI data bus (PCI_EN pin = 0) Used for transfer of data, address, and control			
HD5/AD5§			 Host-Port bus width user-configurable at device reset via a 10-kΩ resistor pullup/pulldown resistor on the HD5 pin: 			
HD4/AD4§	I/O/Z		HD5 pin = 0: HPI operates as an HPI16.			
HD3/AD3§	1/0/2		(HPI bus is 16 bits wide. HD[15:0] pins are used and the remaining HD[31:16] pins are reserved pins in the high-impedance state.)			
HD2/AD2§			HD5 pin = 1: HPI operates as an HPI32.			
HD1/AD1§			(HPI bus is 32 bits wide. All HD[31:0] pins are used for host-port operations.)			
HD0/AD0§]		As PCI data-address bus (PCI_EN pin = 1) Used for transfer of data and address			
PCBE0§	I/O/Z		PCI command/byte enable 0 (I/O/Z). When PCI is disabled (PCI_EN = 0), this pin is tied-off.			
XSP_CS	0	IPD	PCI serial interface chip select (O). When PCI is disabled (PCI_EN = 0), this pin is tied-off.			
XSP_CLK	I/O/Z	IPD	This pin has no function at default [default] or when PCI is enabled (PCI_EN = 0), this pin is the PCI serial interface clock (0).			
XSP_DI	I	IPU	This pin has no function at default [default] or when PCI is enabled (PCI_EN = 0), this pin is the PCI serial interface data in (I). In PCI mode, this pin is connected to the output data pin of the serial PROM.			
XSP_DO	O/Z	IPU	This pin has no function at default [default] or when PCI is enabled (PCI_EN = 0), this pin is the PCI serial interface data out (O). In PCI mode, this pin is connected to the input data pin of the serial PROM.			
GP15/PRST§			General-purpose input/output (GPIO) 15 pin (I/O/Z) or PCI reset (I). No function at default.			
GP14/PCLK§	1		GPIO 14 pin (I/O/Z) or PCI clock (I). No function at default.			
GP13/PINTA§	1		GPIO 13 pin (I/O/Z) or PCI interrupt A (O/Z). No function at default.			
GP12/PGNT§	I/O/Z		GPIO 12 pin (I/O/Z) or PCI bus grant (I). No function at default.			
GP11/PREQ§			GPIO 11 pin (I/O/Z) or PCI bus request (O/Z). No function at default.			
GP10/PCBE3§			GPIO 10 pin (I/O/Z) or PCI command/byte enable 3 (I/O/Z). No function at default.			
GP9/PIDSEL§			GPIO 9 pin (I/O/Z) or PCI initialization device select (I). No function at default.			
CE3	O/Z	IPU				
CE2	O/Z	IPU	EMIF memory space enables			
CE1	O/Z	IPU	 Enabled by bits 28 through 31 of the word address Only one pin is asserted during any external data access 			
CE0	O/Z	IPU	, ,			

[†] I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



[‡] IPD = Internal pulldown, IPU = Internal pullup. (These IPD/IPU signal pins feature a 30-kΩ IPD or IPU resistor. To pull up a signal to the opposite supply rail, a 1-kΩ resistor should be used, unless otherwise noted.)

[§] These pins are multiplexed pins. For more details, see the Device Configurations section of this data sheet.

SPRS196 - MARCH 2002

SIGNAL		Ι	IDD/	Terminar Fanotions (Continued)				
NAME	NO.	TYPET	IPD/ IPU‡	DESCRIPTION				
EMIF (32-bit) - CONTROL SIGNALS COMMON TO ALL TYPES OF MEMORY (CONTINUED)								
BE3		O/Z	IPU	EMIF byte-enable control				
BE2		O/Z	IPU	Decoded from the low-order address bits. The number of address bits or byte enables				
BE1		O/Z	IPU	used depends on the width of external memory. • Byte-write enables for most types of memory				
BE0		O/Z	IPU	Can be directly connected to SDRAM read and write mask signal (SDQM)				
PDT		O/Z	IPU	EMIF peripheral data transfer, allows direct transfer between external peripherals				
				EMIF (32-BIT) – BUS ARBITRATION				
HOLDA		0	IPU	EMIF hold-request-acknowledge to the host				
HOLD		I	IPU	EMIF hold request from the host				
BUSREQ		0	IPU	EMIF bus request output				
		EMIF ((32-BIT) –	ASYNCHRONOUS/SYNCHRONOUS MEMORY CONTROL				
=======================================				EMIF clock mode select				
ECLKIN_SEL1				ECLIVINI SELITADI: 00 ECLIVINI (default mode)				
		I/O/Z	IPD	ECLKIN_SEL[1:0]: 00 - ECLKIN (default mode) 01 - CPU/4 Clock Rate				
ECLKIN_SEL0				10 - CPU/6 Clock Rate				
				11 – Reserved				
ECLKIN			IPD	EMIF external input clock. The EMIF input clock (ECLKIN, CPU/4 clock, or CPU/6 clock) is selected at reset via the pullup/pulldown resistors on the ECLKIN_SEL[1:0] pins.				
ECLKIN		'	I IPD	ECLKIN is the default for the EMIF input clock.				
FOLKOUTO		0/7	IDD	EMIF output clock 2. Programmable to be EMIF input clock (ECLKIN, CPU/4 clock, or CPU/6				
ECLKOUT2		O/Z	IPD	clock) frequency divided-by-1, -2, or -4.				
ECLKOUT1		O/Z	IPD	EMIF output clock 1 at EMIF input clock (ECLKIN, CPU/4 clock, or CPU/6 clock)				
EOLICOTT		0/2	" "	frequency.				
				EMIF asynchronous memory read-enable/SDRAM column-address strobe/programmable synchronous interface-address strobe or read-enable				
ARE/				For programmable synchronous interface, the RENEN field in the CE Space Secondary				
SDCAS/ SADS/SRE		O/Z	IPU	Control Register (CExSEC) selects between SADS and SRE:				
SADS/SKE				If RENEN = 0, then the $\overline{SADS/SRE}$ signal functions as the \overline{SADS} signal.				
				If RENEN = 1, then the SADS/SRE signal functions as the SRE signal.				
AOE/ SDRAS/		0/7	IPU	EMIF asynchronous memory output-enable/SDRAM row-address strobe/programmable				
SOE		O/Z	I IPU	synchronous interface output-enable				
AWE/				ENIE				
SDWE/		O/Z	IPU	EMIF asynchronous memory write-enable/SDRAM write-enable/programmable synchronous interface write-enable				
SWE				Synonionous interface white enable				
SDCKE		O/Z	IPU	EMIF SDRAM clock-enable (used for self-refresh mode).				
				If SDRAM is not in system, SDCKE can be used as a general-purpose output. The content of				
SOE3		O/Z	IPU	EMIF synchronous memory output-enable for CE3 (for glueless FIFO interface)				
ARDY		I	IPU	Asynchronous memory ready input				

[†] I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



[‡] IPD = Internal pulldown, IPU = Internal pullup. (These IPD/IPU signal pins feature a 30-k Ω IPD or IPU resistor. To pull up a signal to the opposite supply rail, a 1-k Ω resistor should be used, unless otherwise noted.)

SPRS196 - MARCH 2002

SIGNAL	TYPET	IPD/ IPU [‡]	DESCRIPTION
NAME NO.	111.2	IPU‡	
			EMIF (32-BIT) – ADDRESS
EA21			
EA20			
EA19			
EA18			
EA17			
EA16			
EA15	4		
EA14	4		
EA13	4		
EA12	O/Z	IPD	EMIF external address (word address)
EA11			
EA10			
EA9			
EA8			
EA7			
EA6			
EA5			
EA4			
EA3			
EA2			
			EMIF (32-bit) – DATA
ED31			
ED30			
ED29			
ED28			
ED27	4		
ED26	1		
ED25	4		
ED24	I/O/Z	IPU	EMIF external data
ED23	,, 5,,2	0	Emil Oxforma data
ED22			
ED21	1		
ED20]		
ED19]		
ED18]		
ED17]		
ED16			

[†] I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



[‡] IPD = Internal pulldown, IPU = Internal pullup. (These IPD/IPU signal pins feature a 30-k Ω IPD or IPU resistor. To pull up a signal to the opposite supply rail, a 1-k Ω resistor should be used, unless otherwise noted.)

SPRS196 - MARCH 2002

SIGNAL	TYPET	IPD/	DESCRIPTION					
NAME N	0.	IPU‡	DESCRIPTION					
	EMIF (32-bit) – DATA (CONTINUED)							
ED15								
ED14								
ED13								
ED12								
ED11								
ED10								
ED9								
ED8	I/O/Z	IPU	EMIF external data					
ED7	1/0/2	IPU	EMIF external data					
ED6								
ED5								
ED4								
ED3								
ED2								
ED1								
ED0								
			TIMER 1					
TOUT1	O/Z	IPD	Timer 1 or general-purpose output					
TINP1	1	IPD	Timer 1 or general-purpose input					
			TIMER 0					
TOUT0	O/Z	IPD	Timer 0 or general-purpose output					
TINP0	1	IPD	Timer 0 or general-purpose input					
		MULTIC	CHANNEL BUFFERED SERIAL PORT 1 (McBSP1)					
CLKS1	1		McBSP1 external clock source (as opposed to internal)					
CLKR1	I/O/Z		McBSP1 receive clock					
CLKX1	I/O/Z		McBSP1 transmit clock					
DR1	I		McBSP1 receive data					
DX1	O/Z		McBSP1 transmit data					
FSR1	I/O/Z		McBSP1 receive frame sync					
FSX1	I/O/Z		McBSP1 transmit frame sync					
		MULTIC	CHANNEL BUFFERED SERIAL PORT 0 (McBSP0)					
CLKS0	I	IPD	McBSP0 external clock source (as opposed to internal)					
CLKR0	I/O/Z	IPD	McBSP0 receive clock					
CLKX0	I/O/Z	IPD	McBSP0 transmit clock					
DR0	- 1	IPU	McBSP0 receive data					
DX0	O/Z	IPU	McBSP0 transmit data					
FSR0	I/O/Z	IPD	McBSP0 receive frame sync					
FSX0	I/O/Z	IPD	McBSP0 transmit frame sync					
t I - Input O - Output	7 – High impod	2000 S -	Supply voltage, GND = Ground					

 $^{^{\}dagger}$ I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



[‡] IPD = Internal pulldown, IPU = Internal pullup. (These IPD/IPU signal pins feature a 30-k Ω IPD or IPU resistor. To pull up a signal to the opposite supply rail, a 1-k Ω resistor should be used, unless otherwise noted.)

SPRS196 - MARCH 2002

SIGNA		TYPET	IPD/	DESCRIPTION
NAME	NO.	111121	IPU‡	
	1			RESERVED FOR TEST
RSV		Z		For proper device operation, these RSV pins (AD11, AD12) must be externally pulled
		Z		down to ground with a 10-kΩ resistor.
RSV			IPD	For proper device operation, this RSV pin (D15) must be externally pulled up to DVDD with a 1-k Ω resistor.
		_		
RSV		4		Reserved. These pins must be connected directly to CV _{DD} for proper device operation.
		4		
RSV				Reserved. This pin must be connected directly to DV _{DD} for proper device operation.
1101	1			Treestived. This pirithiast be defined to a directly to by DD for proper device operation.
			IPD	
			IPU	
-			IPD	
			IPU	
			IPU	1
			IPD	
RSV			IPU	Reserved (leave unconnected, <i>do not</i> connect to power or ground)
NOV			IPU	Reserved (leave directinected, ab hot confinent to power or ground)
			IPU	
			IPU	
			IPD	
			IPD	
		Z		
			IPU	
			IPU	
			IPU	
		-	IPD	-
		Z		-
		Z		1
		Z		1
		Z		1

[†] I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



[‡] IPD = Internal pulldown, IPU = Internal pullup. (These IPD/IPU signal pins feature a 30-kΩ IPD or IPU resistor. To pull up a signal to the opposite supply rail, a 1-kΩ resistor should be used, unless otherwise noted.)

SPRS196 - MARCH 2002

SIGNAL		1		Terminal Functions (Continued)
NAME	NO.	TYPET	IPD/ IPU‡	DESCRIPTION
IAVIAIT	110.	<u> </u>	0.	RESERVED FOR TEST (CONTINUED)
			IPU	
			IPU	
		<u> </u>	IPU	
		<u> </u>	IPU	
			IPU	
		Z		
		Z		
		Z		
		Z		
		Z		
		Z		
		Z		
			IPU	
		Z		
		Z		
RSV		Z		Reserved (leave unconnected, <i>do not</i> connect to power or ground)
		Z		
		Z		
		Z		
		Z		
			IPU	
		-	IPU	
		ļ	IPU	
		-	IPU	
		Z	IPD	
		Z		
		Z Z		
		Z		
		Z		
			IPU	
			IPU	
		 	IPU	
		 	IPU	
		<u> </u>	11 0	

[†] I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground

[‡] IPD = Internal pulldown, IPU = Internal pullup. (These IPD/IPU signal pins feature a 30-kΩ IPD or IPU resistor. To pull up a signal to the opposite supply rail, a 1-kΩ resistor should be used, unless otherwise noted.)



SPRS196 - MARCH 2002

SIGNAL			IPD/	Terminal Functions (Continued)
NAME	NO.	TYPET	IPD/ IPU [‡]	DESCRIPTION
			1	RESERVED FOR TEST (CONTINUED)
			IPU	
			IPD	
			IPD	
			IPU	
			IPD	
			IPU	
			IPU IPU	
RSV			IPD	Reserved (leave unconnected, <i>do not</i> connect to power or ground)
			IPD	
			IPD	
			IPD	
			IPU	
			IPD	
			IPD	
			IPU	
			IPD	
			IPD	
			IPD	
			IPU	

[†] I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



[‡] IPD = Internal pulldown, IPU = Internal pullup. (These IPD/IPU signal pins feature a 30-k Ω IPD or IPU resistor. To pull up a signal to the opposite supply rail, a 1-k Ω resistor should be used, unless otherwise noted.)

SPRS196 - MARCH 2002

SIGNAL	_	TVDET	IPD/	DECODITED
NAME	NO.	TYPET	IPU‡	DESCRIPTION
				RESERVED FOR TEST (CONTINUED)
			IPD	
			IPU	
RSV			IPU	Reserved (leave unconnected, <i>do not</i> connect to power or ground)
			IPU	
			IPU	
			IPU IPU	
			IPD	
			IPU	

[†] I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



[‡] IPD = Internal pulldown, IPU = Internal pullup. (These IPD/IPU signal pins feature a 30-kΩ IPD or IPU resistor. To pull up a signal to the opposite supply rail, a 1-kΩ resistor should be used, unless otherwise noted.)

SPRS196 - MARCH 2002

CIONA		SIGNAL								
NAME	NO.	TYPET	DESCRIPTION							
NAME	140.		SUPPLY VOLTAGE PINS							
DVDD		S	3.3-V supply voltage							

[†] I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



PRODUCT PREVIEW

2121111		ı	Terminal Functions (Continued)
SIGNA		TYPET	DESCRIPTION
NAME	NO.		SUPPLY VOLTAGE PINS (CONTINUED)
DV _{DD}			3.3-V supply voltage
CVDD		S	1-V supply voltage

[†] I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



SPRS196 - MARCH 2002

SIGNAI	L	_	Terminar unctions (continued)
NAME	NO.	TYPET	DESCRIPTION
			SUPPLY VOLTAGE PINS (CONTINUED)
CVDD		S	1-V supply voltage

[†] I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



		1	Terminal Functions (Continued)
SIGNAI NAME	NO.	TYPET	DESCRIPTION
			GROUND PINS
Vss		GND	Ground pins

[†] I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground

SPRS196 - MARCH 2002

SIGNA	L	1	Terminari unctions (continueu)
NAME	NO.	TYPET	DESCRIPTION
			GROUND PINS (CONTINUED)
Vss		GND	Ground pins

[†] I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



SPRS196 - MARCH 2002

Terminal Functions (Continued)

SIGNA	L	TVDET	DECORPTION
NAME	NO.	TYPET	DESCRIPTION
			GROUND PINS (CONTINUED)
Vss		GND	Ground pins

† I = Input, O = Output, Z = High impedance, S = Supply voltage, GND = Ground



SPRS196 - MARCH 2002

development support

TI offers an extensive line of development tools for the TMS320C6000™ DSP platform, including tools to evaluate the performance of the processors, generate code, develop algorithm implementations, and fully integrate and debug software and hardware modules.

The following products support development of C6000™ DSP-based applications:

Software Development Tools:

Code Composer Studio™ Integrated Development Environment (IDE): including Editor C/C++/Assembly Code Generation, and Debug plus additional development tools Scalable, Real-Time Foundation Software (DSP BIOS), which provides the basic run-time target software needed to support any DSP application.

Hardware Development Tools:

Extended Development System (XDS™) Emulator (supports C6000™ DSP multiprocessor system debug) EVM (Evaluation Module)

The *TMS320 DSP Development Support Reference Guide* (SPRU011) contains information about development-support products for all TMS320™ DSP family member devices, including documentation. See this document for further information on TMS320™ DSP documentation or any TMS320™ DSP support products from Texas Instruments. An additional document, the *TMS320 Third-Party Support Reference Guide* (SPRU052), contains information about TMS320™ DSP-related products from other companies in the industry. To receive TMS320™ DSP literature, contact the Literature Response Center at 800/477-8924.

For a complete listing of development-support tools for the TMS320C6000™ DSP platform, visit the Texas Instruments web site on the Worldwide Web at http://www.ti.com uniform resource locator (URL). For information on pricing and availability, contact the nearest TI field sales office or authorized distributor.



device and development-support tool nomenclature

To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all TMS320™ DSP devices and support tools. Each TMS320™ DSP family member has one of three prefixes: TMX, TMP, or TMS. Texas Instruments recommends two of three possible prefix designators for support tools: TMDX and TMDS. These prefixes represent evolutionary stages of product development from engineering prototypes (TMX/TMDX) through fully qualified production devices/tools (TMS/TMDS).

Device development evolutionary flow:

TMX Experimental device that is not necessarily representative of the final device's electrical

specifications

TMP Final silicon die that conforms to the device's electrical specifications but has not completed

quality and reliability verification

TMS Fully qualified production device

Support tool development evolutionary flow:

TMDX Development-support product that has not yet completed Texas Instruments internal qualification

testing.

TMDS Fully qualified development-support product

TMX and TMP devices and TMDX development-support tools are shipped against the following disclaimer:

"Developmental product is intended for internal evaluation purposes."

TMS devices and TMDS development-support tools have been characterized fully, and the quality and reliability of the device have been demonstrated fully. TI's standard warranty applies.

Predictions show that prototype devices (TMX or TMP) have a greater failure rate than the standard production devices. Texas Instruments recommends that these devices not be used in any production system because their expected end-use failure rate still is undefined. Only qualified production devices are to be used.

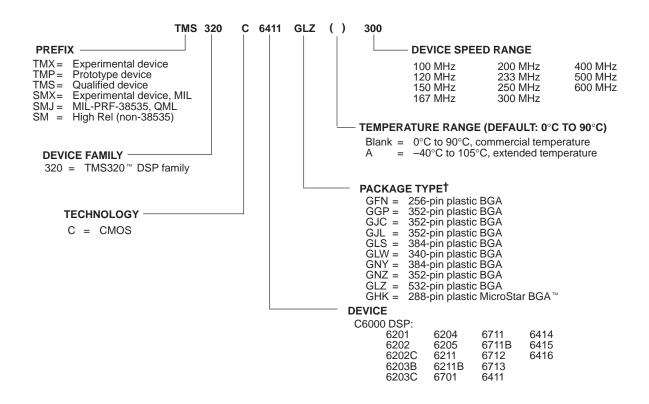
To designate the stages in the product development cycle, TI assigns prefixes to the part numbers of all TMS320™ DSP devices and support tools. Each TMS320™ DSP family member has one of three prefixes: TMX, TMP, or TMS. Texas Instruments recommends two of three possible prefix designators for support tools: TMDX and TMDS. These prefixes represent evolutionary stages of product development from engineering prototypes (TMX/TMDX) through fully qualified production devices/tools (TMS/TMDS).

TI device nomenclature also includes a suffix with the device family name. This suffix indicates the package type (for example, GLZ), the temperature range (for example, blank is the default commercial temperature range), and the device speed range in megahertz (for example, -300 is 300 MHz). Figure 4 provides a legend for reading the complete device name for any TMS320C6000TM DSP platform member.



SPRS196 - MARCH 2002

device and development-support tool nomenclature (continued)



†BGA = Ball Grid Array

Figure 4. TMS320C6000™ DSP Device Nomenclature (Including the TMS320C6411 Device)



SPRS196 - MARCH 2002

documentation support

Extensive documentation supports all TMS320TM DSP family generations of devices from product announcement through applications development. The types of documentation available include: data sheets, such as this document, with design specifications; complete user's reference guides for all devices and tools; technical briefs; development-support tools; on-line help; and hardware and software applications. The following is a brief, descriptive list of support documentation specific to the C6000TM DSP devices:

The *TMS320C6000 CPU and Instruction Set Reference Guide* (literature number SPRU189) describes the C6000™ DSP CPU (core) architecture, instruction set, pipeline, and associated interrupts.

The *TMS320C6000 Peripherals Reference Guide* (literature number SPRU190) describes the functionality of the peripherals available on the C6000™ DSP platform of devices, such as the 64-/32-/16-bit external memory interfaces (EMIFs), direct-memory-access (DMA), enhanced direct-memory-access (EDMA) controller, multichannel buffered serial ports (McBSPs), an 8-bit Universal Test and Operations PHY Interface for ATM Slave (UTOPIA Slave) port, 32-/16-bit host-port interfaces (HPIs), a peripheral component interconnect (PCI), expansion bus (XB), peripheral component interconnect (PCI), clocking and phase-locked loop (PLL); general-purpose timers, general-purpose input/output (GPIO) port, and power-down modes. This guide also includes information on internal data and program memories.

The *TMS320C6000 Technical Brief* (literature number SPRU197) gives an introduction to the C62x[™]/C67x[™] devices, associated development tools, and third-party support.

The *TMS320C64x Technical Overview* (literature number SPRU395) gives an introduction to the C64x[™] digital signal processor, and discusses the application areas that are enhanced by the C64x[™] DSP VelociTI.2[™] VLIW architecture.

The *TMS320C6414 Fixed-Point Digital Signal Processor* data sheet (literature number SPRS134) describes the features of the TMS320C6414 fixed-point DSP and provides pinouts, electrical specifications, and timings for the device.

The *TMS320C6416 Fixed-Point Digital Signal Processor* data sheet (literature number SPRS164) describes the features of the TMS320C6416 fixed-point DSP and provides pinouts, electrical specifications, and timings for the device.

The tools support documentation is electronically available within the Code Composer Studio™ Integrated Development Environment (IDE). For a complete listing of C6000™ DSP latest documentation, visit the Texas Instruments web site on the Worldwide Web at http://www.ti.com uniform resource locator (URL).

See the Worldwide Web URL for Texas Instruments for more detailed information on the device compatibility and similarities/differences among the C6211, C6411, C6414, C6415, and C6416 devices, see the *How To Begin Development Today With the TMS320C6414, TMS320C6415, and TMS320C6416 DSPs* application report (literature number SPRA718) and *How To Begin Development Today With the TMS320C6411 DSP* application report (literature number SPRA374).



SPRS196 - MARCH 2002

clock PLL

Most of the internal C64x[™] DSP clocks are generated from a single source through the CLKIN pin. This source clock either drives the PLL, which multiplies the source clock frequency to generate the internal CPU clock, or bypasses the PLL to become the internal CPU clock.

To use the PLL to generate the CPU clock, the external PLL filter circuit must be properly designed. Figure 5 shows the external PLL circuitry for either x1 (PLL bypass) or other PLL multiply modes.

To minimize the clock jitter, a single clean power supply should power both the C64x™ DSP device and the external clock oscillator circuit. The minimum CLKIN rise and fall times should also be observed. For the input clock timing requirements, see the *input and output clocks* electricals section.

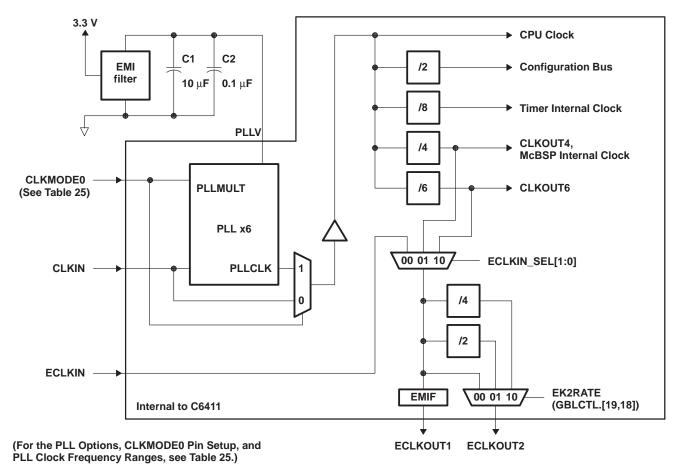
Rise/fall times, duty cycles (high/low pulse durations), and the load capacitance of the external clock source must meet the DSP requirements in this data sheet (see the *electrical characteristics over recommended ranges of suppy voltage and operating case temperature* table and the *input and output clocks* electricals section). Table 24 lists some examples of compatible CLKIN external clock sources:

Table 24. Compatible CLKIN External Clock Sources

COMPATIBLE PARTS FOR EXTERNAL CLOCK SOURCES (CLKIN)	PART NUMBER	MANUFACTURER
	JITO-2	Fox Electronix
One Western	STA series, ST4100 series	SaRonix Corporation
Oscillators	SG-636	Epson America
	342	Corning Frequency Control
PLL	PLL MK1711-S, ICS525-02 Integrated C	



clock PLL (continued)



- NOTES: A. Place all PLL external components (C1, C2, and the EMI Filter) as close to the C6000™ DSP device as possible. For the best performance, TI recommends that all the PLL external components be on a single side of the board without jumpers, switches, or components other than the ones shown.
 - B. For reduced PLL jitter, maximize the spacing between switching signals and the PLL external components (C1, C2, and the EMI Filter).
 - C. The 3.3-V supply for the EMI filter must be from the same 3.3-V power plane supplying the I/O voltage, DV_{DD}.
 - D. EMI filter manufacturer TDK part number ACF451832-333, -223, -153, -103. Panasonic part number EXCET103U.

Figure 5. External PLL Circuitry for Either PLL Multiply Modes or x1 (Bypass) Mode



SPRS196 - MARCH 2002

clock PLL (continued)

Table 25. TMS320C6411 PLL Multiply Factor Options, Clock Frequency Ranges, and Typical Lock Time†‡

	GLZ PACKAGE – 23 x 23 mm BGA							
CLKMODE0	CLKMODE (PLL MULTIPLY FACTORS)	CLKIN CPU CLOCK RANGE FREQUENCY (MHz) RANGE (MHz)		CLKOUT4 RANGE (MHz)	CLKOUT6 RANGE (MHz)	TYPICAL LOCK TIME (μs)§		
0	Bypass (x1) [default]	30–75	30–75	7.5–18.8	5–12.5	N/A		
1	х6	30–50	180–300	45–75	30–50	75		

[†] These clock frequency range values are applicable to a C6411–300 speed device.



Use an external pullup resistor on the CLKMODE0 pin to set the C6411 device to the valid PLL multiply clock mode (x6). With an internal pulldown resistor on the CLKMODE0 pin, the default clock mode is x1 (bypass).

[§] Under some operating conditions, the maximum PLL lock time may vary by as much as 150% from the specified typical value. For example, if the typical lock time is specified as 100 μs, the maximum value may be as long as 250 μs.

SPRS196 - MARCH 2002

TMS320C6411 FIXED-POINT DIGITAL SIGNAL PROCESSOR

power-supply sequencing

TI DSPs do not require specific power sequencing between the core supply and the I/O supply. However, systems should be designed to ensure that neither supply is powered up for extended periods of time if the other supply is below the proper operating voltage.

system-level design considerations

System-level design considerations, such as bus contention, may require supply sequencing to be implemented. In this case, the core supply should be powered up at the same time as, or prior to (and powered down after), the I/O buffers. This is to ensure that the I/O buffers receive valid inputs from the core before the output buffers are powered up, thus, preventing bus contention with other chips on the board.

power-supply design considerations

A dual-power supply with simultaneous sequencing can be used to eliminate the delay between core and I/O power up. A Schottky diode can also be used to tie the core rail to the I/O rail.

Core and I/O supply voltage regulators should be located close to the DSP (or DSP array) to minimize inductance and resistance in the power delivery path. Additionally, when designing for high-performance applications utilizing the C6000™ platform of DSPs, the PC board should include separate power planes for core, I/O, and ground, all bypassed with high-quality low-ESL/ESR capacitors.



SPRS196 - MARCH 2002

absolute maximum ratings over operating case temperature range (unless otherwise noted)

Supply voltage ranges:	CV _{DD} (see Note 1)	– 0.3 V to 2.3 V
	DV _{DD} (see Note 1)	0.3 V to 4 V
Input voltage ranges:	(except PCI), V _I	0.3 V to 4 V
	(PCI), V _{IP}	0.5 V to DV _{DD} + 0.5 V
Output voltage ranges:	(except PCI), VO	
	(PCI), V _{OP}	0.5 V to DV _{DD} + 0.5 V
Operating case tempera	ature range, T _C	0°C to 90°C
Storage temperature ra	nge, T _{stg}	65°C to 150°C

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTE 1: All voltage values are with respect to VSS.

recommended operating conditions

			MIN	NOM	MAX	UNIT
CV _{DD}	Supply voltage, Core‡		0.97	1	1.03	V
DV_{DD}	Supply voltage, I/O		3.14	3.3	3.46	V
VSS	Supply ground		0	0	0	V
VIH	High-level input voltage (exception)	pt PCI)	2			V
V _{IL}	Low-level input voltage (excep	ot PCI)			0.8	V
V_{IP}	Input voltage (PCI)		-0.5		DV _{DD} + 0.5	
V_{IHP}	High-level input voltage (PCI)		0.5DV _{DD}		DV _{DD} + 0.5	V
V_{ILP}	Low-level input voltage (PCI)		-0.5		3.3 3.46 0 0 0.8 DV _{DD} + 0.5	
	I Pak Javal autout avenuet	except CLKOUT4 and CLKOUT6			-8	mA
IOH	High-level output current	CLKOUT4 and CLKOUT6			0.8 DV _{DD} + 0.5 DV _{DD} + 0.5 0.3DV _{DD} -8 -16 8 16	mA
		except CLKOUT4 and CLKOUT6		8		mA
lOL	Low-level output current	CLKOUT4 and CLKOUT6			16	mA
T _C	Operating case temperature		0		90	°C

[‡] Future variants of the C6411 DSP may operate at voltages ranging from 1.0 V to 1.4 V to provide a range of system power/performance options. TI highly recommends that users design-in a supply that can handle multiple voltages within this range (i.e., 1.0 V, 1.1 V, 1.2 V, 1.3 V, 1.4 V with ± 3% tolerances) by implementing simple board changes such as reference resistor values or input pin configuration modifications. Examples of such supplies include the PT4660, PT5500, PT5520, PT6440, and PT6930 series from Power Trends, a subsidiary of Texas Instruments. Not incorporating a flexible supply may limit the system's ability to easily adapt to future versions of C641x devices.



SPRS196 - MARCH 2002

TMS320C6411

electrical characteristics over recommended ranges of supply voltage and operating case temperature (unless otherwise noted)

	PARAMETER	TEST COND	ITIONS†	MIN	TYP	MAX	UNIT
Vон	High-level output voltage (except PCI)	$DV_{DD} = MIN,$	$I_{OH} = MAX$	2.4			V
VOHP	High-level output voltage (PCI)	$I_{OHP} = -0.5 \text{ mA},$	3.3 V	0.9DV _{DD}			V
VOL	Low-level output voltage (except PCI)	$DV_{DD} = MIN,$	$I_{OL} = MAX$			0.4	V
VOLP	Low-level output voltage (PCI)	$I_{OLP} = 1.5 \text{ mA},$	3.3 V			0.1DV _{DD}	V
II	Input current (except PCI)	$V_I = V_{SS}$ to DV_{DD}				±150	uA
lιΡ	Input leakage current (PCI)‡	$0 < V_{IP} < DV_{DD}$	3.3 V			±10	uA
loz	Off-state output current	$V_O = DV_{DD}$ or 0 V				±10	uA
ICDD	Core supply current§	CV _{DD} = 1 V, CPU clo	ock = 300 MHz		TBD		mA
IDDD	I/O supply current§	$DV_{DD} = 3.3 \text{ V, CPU}$	clock = 300 MHz		125		mA
Ci	Input capacitance					10	pF
Co	Output capacitance					10	pF

[†] For test conditions shown as MIN, MAX, or NOM, use the appropriate value specified in the recommended operating conditions table.

[‡] PCI input leakage currents include Hi-Z output leakage for all bidirectional buffers with 3-state outputs.

[§] Measured with average activity (50% high/50% low power). The actual current draw is highly application-dependent. For more details on core and I/O activity, refer to the *TMS320C6411 Power Consumption Summary* application report (literature number SPRA373).

PARAMETER MEASUREMENT INFORMATION

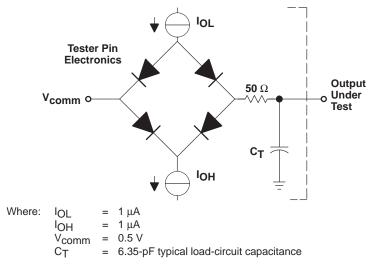


Figure 6. Test Load Circuit for AC Timing Measurements

signal transition levels

All input and output timing parameters are referenced to 1.5 V for both "0" and "1" logic levels.



Figure 7. Input and Output Voltage Reference Levels for AC Timing Measurements

All rise and fall transition timing parameters are referenced to V_{IL} MAX and V_{IH} MIN for input clocks, V_{OL} MAX and V_{OHP} MIN for output clocks, V_{ILP} MAX and V_{IHP} MIN for PCI input clocks, and V_{OLP} MAX and V_{OHP} MIN for PCI output clocks.

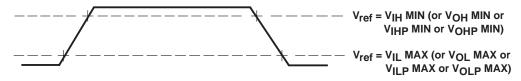


Figure 8. Rise and Fall Transition Time Voltage Reference Levels

PARAMETER MEASUREMENT INFORMATION (CONTINUED)

timing parameters and board routing analysis

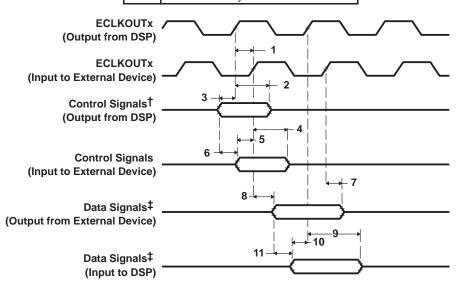
The timing parameter values specified in this data sheet do *not* include delays by board routings. As a good board design practice, such delays must *always* be taken into account. Timing values may be adjusted by increasing/decreasing such delays. TI recommends utilizing the available I/O buffer information specification (IBIS) models to analyze the timing characteristics correctly. If needed, external logic hardware such as buffers may be used to compensate any timing differences.

For inputs, timing is most impacted by the round-trip propagation delay from the DSP to the external device and from the external device to the DSP. This round-trip delay tends to negatively impact the input setup time margin, but also tends to improve the input hold time margins (see Table 26 and Figure 9).

Figure 9 represents a general transfer between the DSP and an external device. The figure also represents board route delays and how they are perceived by the DSP and the external device.

Table 26. IBIS Timing Parameters Example (see Figure 9)

NO.	DESCRIPTION
1	Clock route delay
2	Minimum DSP hold time
3	Minimum DSP setup time
4	External device hold time requirement
5	External device setup time requirement
6	Control signal route delay
7	External device hold time
8	External device access time
9	DSP hold time requirement
10	DSP setup time requirement
11	Data route delay



[†] Control signals include data for Writes.

Figure 9. IBIS Input/Output Timings



 $[\]ensuremath{\ddagger}$ Data signals are generated during Reads from an external device.

INPUT AND OUTPUT CLOCKS

timing requirements for CLKIN†‡§ (see Figure 10)

				-3	00		
NO.			PLL MODE x6		x1 (BYPASS)		UNIT
			MIN	MAX	MIN	MAX	
1	tc(CLKIN)	Cycle time, CLKIN					ns
2	tw(CLKINH)	Pulse duration, CLKIN high					ns
3	tw(CLKINL)	Pulse duration, CLKIN low					ns
4	t _t (CLKIN)	Transition time, CLKIN					ns

[†] The reference points for the rise and fall transitions are measured at V_{IL} MAX and V_{IH} MIN.

 $[\]S$ C = CLKIN cycle time in ns. For example, when CLKIN frequency is 50 MHz, use C = 20 ns.

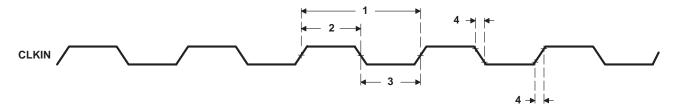


Figure 10. CLKIN Timing

[‡] For more details on the PLL multiplier factor (x6), see the *Clock PLL* section of this data sheet.

INPUT AND OUTPUT CLOCKS (CONTINUED)

switching characteristics over recommended operating conditions for CLKOUT4^{†‡§} (see Figure 11)

			-3		
NO.		PARAMETER	CLKMOD	E = x1, x6	UNIT
			MIN	MAX	1
1	tc(CKO4)	Cycle time, CLKOUT4			ns
2	tw(CKO4H)	Pulse duration, CLKOUT4 high			ns
3	tw(CKO4L)	Pulse duration, CLKOUT4 low			ns
4	t _t (CKO4)	Transition time, CLKOUT4			ns

[†] The reference points for the rise and fall transitions are measured at VOL MAX and VOH MIN.

[§] P = 1/CPU clock frequency in nanoseconds (ns)

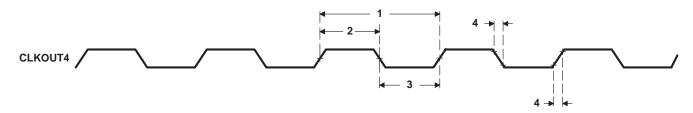


Figure 11. CLKOUT4 Timing

switching characteristics over recommended operating conditions for CLKOUT6^{†‡§} (see Figure 12)

			-3			
NO.	PARAMETER			CLKMODE = x1, x6		
		MIN	MAX	1		
1	t _c (CKO6)	Cycle time, CLKOUT6			ns	
2	tw(CKO6H)	Pulse duration, CLKOUT6 high			ns	
3	tw(CKO6L)	Pulse duration, CLKOUT6 low			ns	
4	t _t (CKO6)	Transition time, CLKOUT6			ns	

[†] The reference points for the rise and fall transitions are measured at VOL MAX and VOH MIN.

[§] P = 1/CPU clock frequency in nanoseconds (ns)

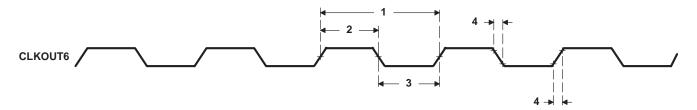


Figure 12. CLKOUT6 Timing



[‡] PH is the high period of CLKIN in ns and PL is the low period of CLKIN in ns.

[‡]PH is the high period of CLKIN in ns and PL is the low period of CLKIN in ns.

INPUT AND OUTPUT CLOCKS (CONTINUED)

timing requirements for ECLKIN†‡ (see Figure 13)

NO.			MIN	MAX	UNIT
1	t _{c(EKI)}	Cycle time, ECLKIN			ns
2	tw(EKIH)	Pulse duration, ECLKIN high			ns
3	tw(EKIL)	Pulse duration, ECLKIN low			ns
4	t _t (EKI)	Transition time, ECLKIN			ns

 $[\]dagger$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

[‡] The reference points for the rise and fall transitions are measured at V_{II} MAX and V_{IH} MIN.

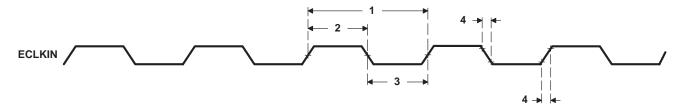


Figure 13. ECLKIN Timing

switching characteristics over recommended operating conditions for ECLKOUT1§¶# (see Figure 14)

NO.	DADAMETER		-300		
		PARAMETER			UNIT
1	t _c (EKO1)	Cycle time, ECLKOUT1			ns
2	tw(EKO1H)	Pulse duration, ECLKOUT1 high			ns
3	tw(EKO1L)	Pulse duration, ECLKOUT1 low			ns
4	t _t (EKO1)	Transition time, ECLKOUT1			ns
5	td(EKIH-EKO1H)	Delay time, ECLKIN high to ECLKOUT1 high			ns
6	td(EKIL-EKO1L)	Delay time, ECLKIN low to ECLKOUT1 low		·	ns

[§] The reference points for the rise and fall transitions are measured at VOL MAX and VOH MIN.

[#]EH is the high period of E (EMIF input clock period) in ns and EL is the low period of E (EMIF input clock period) in ns.

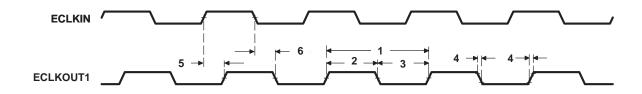


Figure 14. ECLKOUT1 Timing



[¶] E = the EMIF input clock (ECLKIN, CPU/4 clock, or CPU/6 clock) period in ns.

INPUT AND OUTPUT CLOCKS (CONTINUED)

switching characteristics over recommended operating conditions for ECLKOUT2^{†‡} (see Figure 15)

NO.	2.2.445752		-300		
		PARAMETER	MIN	MAX	UNIT
1	t _c (EKO2)	Cycle time, ECLKOUT2			ns
2	tw(EKO2H)	Pulse duration, ECLKOUT2 high			ns
3	tw(EKO2L)	Pulse duration, ECLKOUT2 low			ns
4	tt(EKO2)	Transition time, ECLKOUT2			ns
5	td(EKIH-EKO2H)	Delay time, ECLKIN high to ECLKOUT2 high			ns
6	td(EKIH-EKO2L)	Delay time, ECLKIN high to ECLKOUT2 low			ns

[†]The reference points for the rise and fall transitions are measured at VOL MAX and VOH MIN.

N =the EMIF input clock divider; N = 1, 2,or 4.

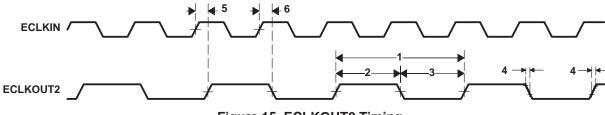


Figure 15. ECLKOUT2 Timing

[‡] E = the EMIF input clock (ECLKIN, CPU/4 clock, or CPU/6 clock) period in ns.

FIXED-POINT DIGITAL SIGNAL PROCESSOR

SPRS196 - MARCH 2002

ASYNCHRONOUS MEMORY TIMING

timing requirements for asynchronous memory cycles^{†‡} (see Figure 16 and Figure 17)

NO.			-300		
			MIN	MAX	UNIT
3	t _{su} (EDV-AREH)	Setup time, EDx valid before ARE high			ns
4	th(AREH-EDV)	Hold time, EDx valid after ARE high			ns
6	tsu(ARDY-EKO1H)	Setup time, ARDY valid before ECLKOUT1 high			ns
7	th(EKO1H-ARDY)	Hold time, ARDY valid after ECLKOUT1 high			ns

[†] To ensure data setup time, simply program the strobe width wide enough. ARDY is internally synchronized. The ARDY signal is recognized in the cycle for which the setup and hold time is met. To use ARDY as an asynchronous input, the pulse width of the ARDY signal should be wide enough (e.g., pulse width = 2E) to ensure setup and hold time is met.

switching characteristics over recommended operating conditions for asynchronous memory cycles^द (see Figure 16 and Figure 17)

NO.		-300	0		
		PARAMETER	MIN	MAX	UNIT
1	tosu(SELV-AREL)	Output setup time, select signals valid to ARE low			ns
2	toh(AREH-SELIV)	Output hold time, ARE high to select signals invalid			ns
5	td(EKO1H-AREV)	Delay time, ECLKOUT1 high to ARE vaild			ns
8	tosu(SELV-AWEL)	Output setup time, select signals valid to AWE low			ns
9	toh(AWEH-SELIV)	Output hold time, AWE high to select signals invalid			ns
10	td(EKO1H-AWEV)	Delay time, ECLKOUT1 high to AWE vaild			ns
11	tosu(PDTV-AREL)	Output setup time, PDT valid to ARE low			ns
12	toh(AREH-PDTIV)	Output hold time, ARE high to PDT invalid			ns
13	tosu(PDTV-AWEV)	Output setup time, PDT valid to AWE valid			ns
14	toh(AWEH-PDTIV)	Output hold time, AWE high to PDT invalid			ns

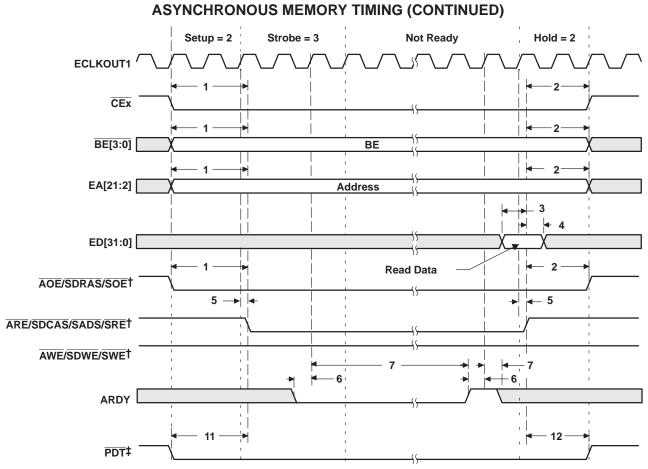
[‡]RS = Read setup, RST = Read strobe, RH = Read hold, WS = Write setup, WST = Write strobe, WH = Write hold. These parameters are programmed via the EMIF CE space control registers.



[‡]RS = Read setup, RST = Read strobe, RH = Read hold, WS = Write setup, WST = Write strobe, WH = Write hold. These parameters are programmed via the EMIF CE space control registers.

[§] E = ECLKOUT1 period in ns

[¶] Select signals for EMIF include: CEx, BE[3:0], EA[21:2], AOE; and for EMIF writes, include ED[31:0].



[†] AOE/SDRAS/SOE, ARE/SDCAS/SADS/SRE, and AWE/SDWE/SWE operate as AOE (identified under select signals), ARE, and AWE, respectively, during asynchronous memory accesses.

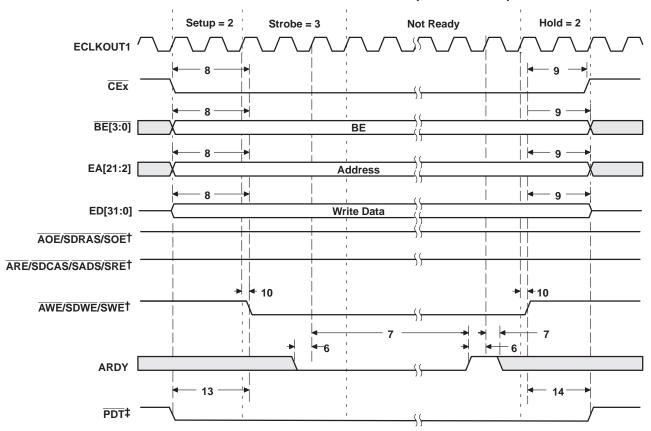
Figure 16. Asynchronous Memory Read Timing



[‡] PDT signal is only asserted when the EDMA is in PDT mode (set the PDTS bit to 1 in the EDMA options parameter RAM). For PDT read, data is not latched into EMIF.

SPRS196 - MARCH 2002

ASYNCHRONOUS MEMORY TIMING (CONTINUED)



[†] AOE/SDRAS/SOE, ARE/SDCAS/SADS/SRE, and AWE/SDWE/SWE operate as AOE (identified under select signals), ARE, and AWE, respectively, during asynchronous memory accesses.

Figure 17. Asynchronous Memory Write Timing



[‡] PDT signal is only asserted when the EDMA is in PDT mode (set the PDTD bit to 1 in the EDMA options parameter RAM). For PDT write, data is not driven (in High-Z).

PROGRAMMABLE SYNCHRONOUS INTERFACE TIMING

timing requirements for programmable synchronous interface cycles (see Figure 18)

NO			-300		
NO.			MIN MAX		UNIT
6	tsu(EDV-EKOxH)	Setup time, read EDx valid before ECLKOUTx high			ns
7	th(EKOxH-EDV)	Hold time, read EDx valid after ECLKOUTx high		·	ns

switching characteristics over recommended operating conditions for programmable synchronous interface cycles[†] (see Figure 18–Figure 20)

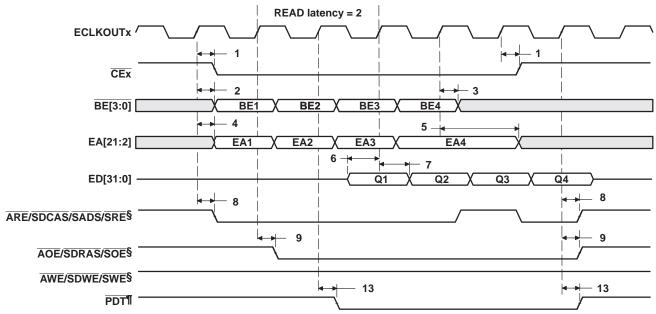
NO.			-300		
		PARAMETER	MIN	MAX	UNIT
1	td(EKOxH-CEV)	Delay time, ECLKOUTx high to CEx valid			ns
2	td(EKOxH-BEV)	Delay time, ECLKOUTx high to BEx valid			ns
3	td(EKOxH-BEIV)	Delay time, ECLKOUTx high to BEx invalid			ns
4	td(EKOxH-EAV)	Delay time, ECLKOUTx high to EAx valid			ns
5	td(EKOxH-EAIV)	Delay time, ECLKOUTx high to EAx invalid			ns
8	td(EKOxH-ADSV)	Delay time, ECLKOUTx high to SADS/SRE valid			ns
9	td(EKOxH-OEV)	Delay time, ECLKOUTx high to, SOE valid			ns
10	td(EKOxH-EDV)	Delay time, ECLKOUTx high to EDx valid			ns
11	td(EKOxH-EDIV)	Delay time, ECLKOUTx high to EDx invalid			ns
12	td(EKOxH-WEV)	Delay time, ECLKOUTx high to SWE valid	·		ns
13	td(EKOxH-PDTV)	Delay time, ECLKOUTx high to PDT valid			ns

[†] The following parameters are programmable via the EMIF CE Space Secondary Control register (CExSEC):

- Read latency (SYNCRL): 0-, 1-, 2-, or 3-cycle read latency
- Write latency (SYNCWL): 0-, 1-, 2-, or 3-cycle write latency
- CEx assertion length (CEEXT): For standard SBSRAM or ZBT SRAM interface, CEx goes inactive after the final command has been issued (CEEXT = 0). For synchronous FIFO interface with glue, CEx is active when SOE is active (CEEXT = 1).
- Function of SADS/SRE (RENEN): For standard SBSRAM or ZBT SRAM interface, SADS/SRE acts as SADS with deselect cycles (RENEN = 0). For FIFO interface, SADS/SRE acts as SRE with NO deselect cycles (RENEN = 1).
- Synchronization clock (SNCCLK): Synchronized to ECLKOUT1 or ECLKOUT2



PROGRAMMABLE SYNCHRONOUS INTERFACE TIMING (CONTINUED)

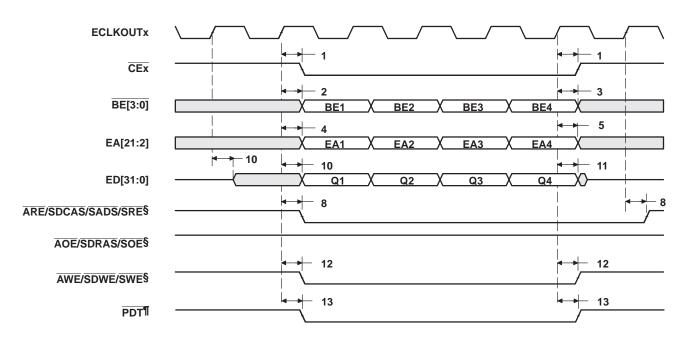


- † The read latency and the length of $\overline{\text{CEx}}$ assertion are programmable via the SYNCRL and CEEXT fields, respectively, in the EMIF CE Space Secondary Control register (CExSEC). In this figure, SYNCRL = 2 and CEEXT = 0.
- [‡]The following parameters are programmable via the EMIF CE Space Secondary Control register (CExSEC):
 - Read latency (SYNCRL): 0-, 1-, 2-, or 3-cycle read latency
 - Write latency (SYNCWL): 0-, 1-, 2-, or 3-cycle write latency
 - CEx assertion length (CEEXT): For standard SBSRAM or ZBT SRAM interface, CEx goes inactive after the final command has been issued (CEEXT = 0). For synchronous FIFO interface with glue, CEx is active when SOE is active (CEEXT = 1).
 - Function of SADS/SRE (RENEN): For standard SBSRAM or ZBT SRAM interface, SADS/SRE acts as SADS with deselect cycles (RENEN = 0). For FIFO interface, SADS/SRE acts as SRE with NO deselect cycles (RENEN = 1).
 - Synchronization clock (SNCCLK): Synchronized to ECLKOUT1 or ECLKOUT2
- § ARE/SDCAS/SADS/SRE, AOE/SDRAS/SOE, and AWE/SDWE/SWE operate as SADS/SRE, SOE, and SWE, respectively, during programmable synchronous interface accesses.
- ¶ PDT signal is only asserted when the EDMA is in PDT mode (set the PDTS bit to 1 in the EDMA options parameter RAM). For PDT read, data is not latched into EMIF.

Figure 18. Programmable Synchronous Interface Read Timing (With Read Latency = 2)^{†‡}



PROGRAMMABLE SYNCHRONOUS INTERFACE TIMING (CONTINUED)



[†] The write latency and the length of $\overline{\text{CEx}}$ assertion are programmable via the SYNCWL and CEEXT fields, respectively, in the EMIF CE Space Secondary Control register (CExSEC). In this figure, SYNCWL = 0 and CEEXT = 0.

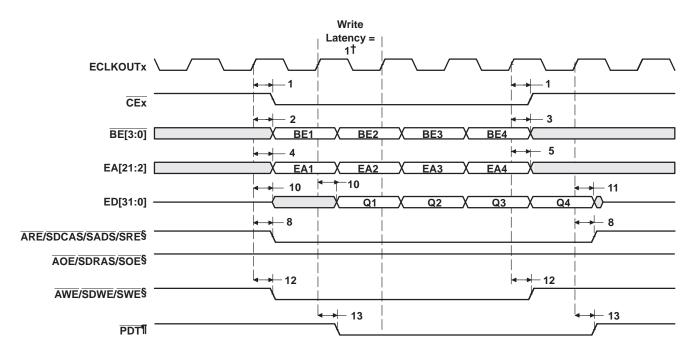
[‡] The following parameters are programmable via the EMIF CE Space Secondary Control register (CEXSEC):

- Read latency (SYNCRL): 0-, 1-, 2-, or 3-cycle read latency
- Write latency (SYNCWL): 0-, 1-, 2-, or 3-cycle write latency
- CEx assertion length (CEEXT): For standard SBSRAM or ZBT SRAM interface, CEx goes inactive after the final command has been issued (CEEXT = 0). For synchronous FIFO interface with glue, CEx is active when SOE is active (CEEXT = 1).
- Function of SADS/SRE (RENEN): For standard SBSRAM or ZBT SRAM interface, SADS/SRE acts as SADS with deselect cycles (RENEN = 0). For FIFO interface, SADS/SRE acts as SRE with NO deselect cycles (RENEN = 1).
- Synchronization clock (SNCCLK): Synchronized to ECLKOUT1 or ECLKOUT2
- § ARE/SDCAS/SADS/SRE, AOE/SDRAS/SOE, and AWE/SDWE/SWE operate as SADS/SRE, SOE, and SWE, respectively, during programmable synchronous interface accesses.
- PDT signal is only asserted when the EDMA is in PDT mode (set the PDTD bit to 1 in the EDMA options parameter RAM). For PDT write, data is not driven (in High-Z).

Figure 19. Programmable Synchronous Interface Write Timing (With Write Latency = 0)†‡



PROGRAMMABLE SYNCHRONOUS INTERFACE TIMING (CONTINUED)



- † The write latency and the length of $\overline{\text{CEx}}$ assertion are programmable via the SYNCWL and CEEXT fields, respectively, in the EMIF CE Space Secondary Control register (CExSEC). In this figure, SYNCWL = 1 and CEEXT = 0.
- ‡The following parameters are programmable via the EMIF CE Space Secondary Control register (CExSEC):
- Read latency (SYNCRL): 0-, 1-, 2-, or 3-cycle read latency
- Write latency (SYNCWL): 0-, 1-, 2-, or 3-cycle write latency
- CEx assertion length (CEEXT): For standard SBSRAM or ZBT SRAM interface, CEx goes inactive after the final command has been issued (CEEXT = 0). For synchronous FIFO interface with glue, CEx is active when SOE is active (CEEXT = 1).
- Function of SADS/SRE (RENEN): For standard SBSRAM or ZBT SRAM interface, SADS/SRE acts as SADS with deselect cycles (RENEN = 0). For FIFO interface, SADS/SRE acts as SRE with NO deselect cycles (RENEN = 1).
- Synchronization clock (SNCCLK): Synchronized to ECLKOUT1 or ECLKOUT2
- § ARE/SDCAS/SADS/SRE, AOE/SDRAS/SOE, and AWE/SDWE/SWE operate as SADS/SRE, SOE, and SWE, respectively, during programmable synchronous interface accesses.
- TDT signal is only asserted when the EDMA is in PDT mode (set the PDTD bit to 1 in the EDMA options parameter RAM). For PDT write, data is not driven (in High-Z).

Figure 20. Programmable Synchronous Interface Write Timing (With Write Latency = 1)^{†‡}



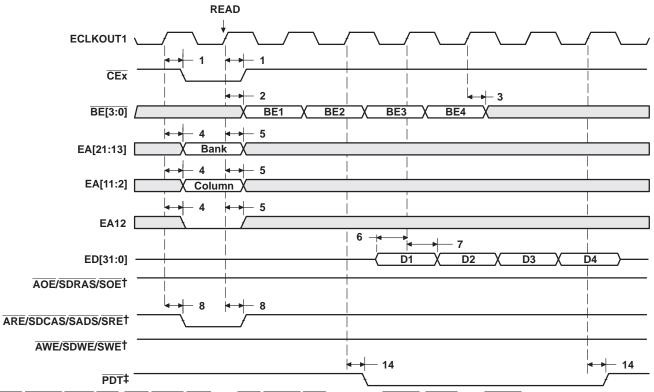
SYNCHRONOUS DRAM TIMING

timing requirements for synchronous DRAM cycles (see Figure 21)

No.			-300		LINUT
NO.			MIN	MAX	UNIT
6	t _{su} (EDV-EKO1H)	Setup time, read EDx valid before ECLKOUT1 high			ns
7	th(EKO1H-EDV)	Hold time, read EDx valid after ECLKOUT1 high			ns

switching characteristics over recommended operating conditions for synchronous DRAM cycles (see Figure 21–Figure 28)

		PARAMETER	-300		
NO.			MIN	MAX	UNIT
1	td(EKO1H-CEV)	Delay time, ECLKOUT1 high to CEx valid			ns
2	td(EKO1H-BEV)	Delay time, ECLKOUT1 high to BEx valid			ns
3	td(EKO1H-BEIV)	Delay time, ECLKOUT1 high to BEx invalid			ns
4	td(EKO1H-EAV)	Delay time, ECLKOUT1 high to EAx valid			ns
5	td(EKO1H-EAIV)	Delay time, ECLKOUT1 high to EAx invalid			ns
8	td(EKO1H-CASV)	Delay time, ECLKOUT1 high to SDCAS valid			ns
9	td(EKO1H-EDV)	Delay time, ECLKOUT1 high to EDx valid			ns
10	td(EKO1H-EDIV)	Delay time, ECLKOUT1 high to EDx invalid			ns
11	td(EKO1H-WEV)	Delay time, ECLKOUT1 high to SDWE valid			ns
12	td(EKO1H-RAS)	Delay time, ECLKOUT1 high to SDRAS valid			ns
13	td(EKO1H-ACKEV)	Delay time, ECLKOUT1 high to SDCKE valid			ns
14	td(EKO1H-PDTV)	Delay time, ECLKOUT1 high to PDT valid			ns

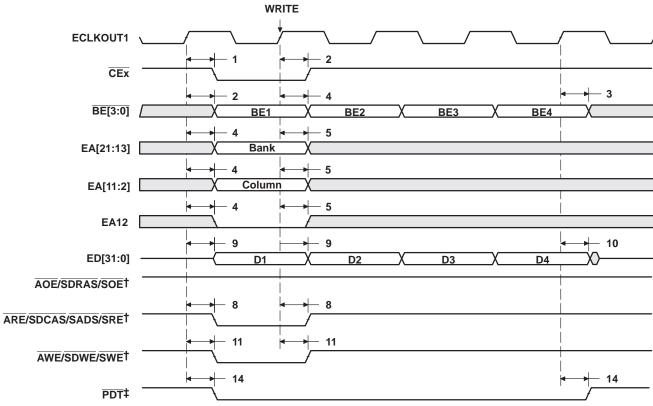


[†] ARE/SDCAS/SADS/SRE, AWE/SDWE/SWE, and AOE/SDRAS/SOE operate as SDCAS, SDWE, and SDRAS, respectively, during SDRAM accesses.

Figure 21. SDRAM Read Command (CAS Latency 3)



[‡] PDT signal is only asserted when the EDMA is in PDT mode (set the PDTS bit to 1 in the EDMA options parameter RAM). For PDT read, data is not latched into EMIF.

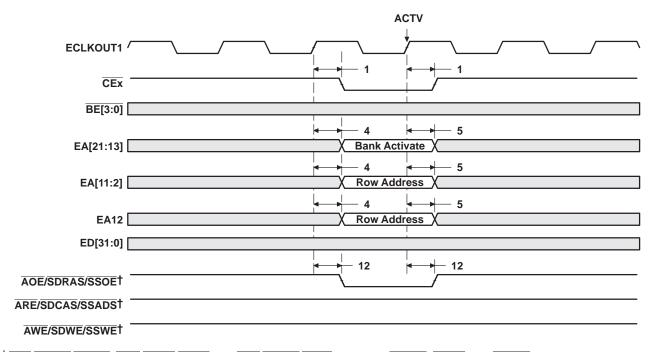


[†] ARE/SDCAS/SADS/SRE, AWE/SDWE/SWE, and AOE/SDRAS/SOE operate as SDCAS, SDWE, and SDRAS, respectively, during SDRAM accesses

Figure 22. SDRAM Write Command

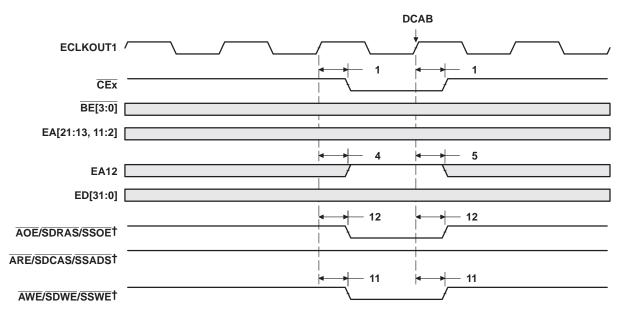


[‡] PDT signal is only asserted when the EDMA is in PDT mode (set the PDTD bit to 1 in the EDMA options parameter RAM). For PDT write, data is not driven (in High-Z).



[†] ARE/SDCAS/SSADS, AWE/SDWE/SSWE, and AOE/SDRAS/SSOE operate as SDCAS, SDWE, and SDRAS, respectively, during SDRAM accesses.

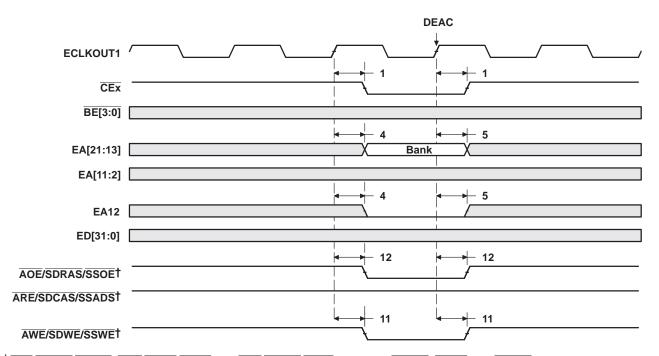
Figure 23. SDRAM ACTV Command



[†] ARE/SDCAS/SSADS, AWE/SDWE/SSWE, and AOE/SDRAS/SSOE operate as SDCAS, SDWE, and SDRAS, respectively, during SDRAM accesses.

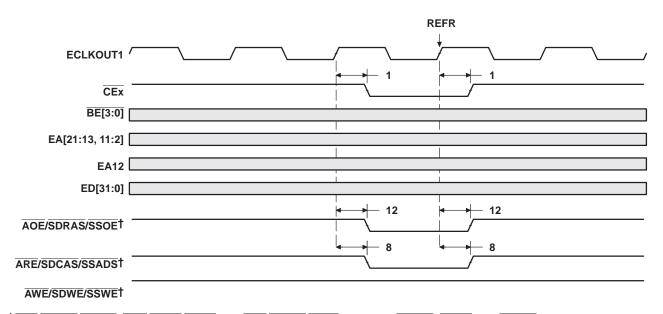
Figure 24. SDRAM DCAB Command





[†] ARE/SDCAS/SSADS, AWE/SDWE/SSWE, and AOE/SDRAS/SSOE operate as SDCAS, SDWE, and SDRAS, respectively, during SDRAM accesses.

Figure 25. SDRAM DEAC Command



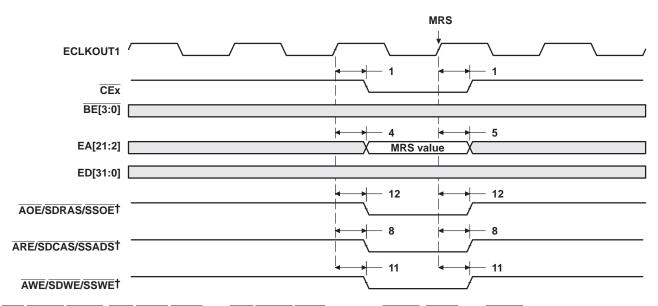
[†] ARE/SDCAS/SSADS, AWE/SDWE/SSWE, and AOE/SDRAS/SSOE operate as SDCAS, SDWE, and SDRAS, respectively, during SDRAM accesses.

Figure 26. SDRAM REFR Command



TMS320C6411 FIXED-POINT DIGITAL SIGNAL PROCESSOR

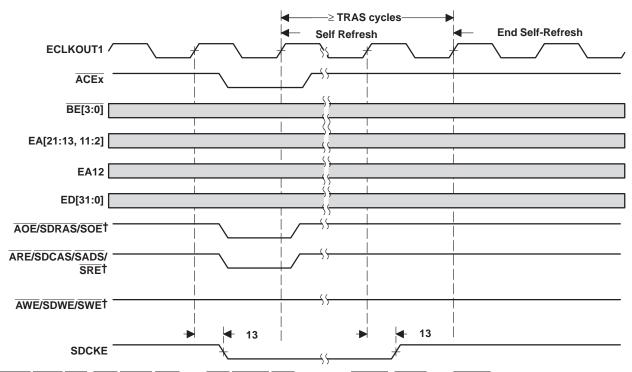
SPRS196 - MARCH 2002



[†] ARE/SDCAS/SSADS, AWE/SDWE/SSWE, and AOE/SDRAS/SSOE operate as SDCAS, SDWE, and SDRAS, respectively, during SDRAM accesses.

Figure 27. SDRAM MRS Command





[†] ARE/SDCAS/SADS/SRE, AWE/SDWE/SWE, and AOE/SDRAS/SOE operate as SDCAS, SDWE, and SDRAS, respectively, during SDRAM accesses.

Figure 28. SDRAM Self-Refresh Timing



HOLD/HOLDA TIMING

timing requirements for the HOLD/HOLDA cycles[†] (see Figure 29)

			-300		
NO.			MIN	MAX	UNIT
3	toh(HOLDAL-HOLDL)	Hold time, HOLD low after HOLDA low			ns

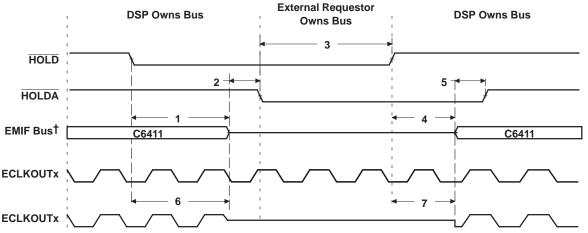
[†]E = the EMIF input clock (ECLKIN, CPU/4 clock, or CPU/6 clock) period in ns.

switching characteristics over recommended operating conditions for the HOLD/HOLDA cycles†‡§ (see Figure 29)

NO	DADAMETED		-300		LINUT
NO.	PARAMETER				UNIT
1	td(HOLDL-EMHZ)	Delay time, HOLD low to EMIF Bus high impedance		¶	ns
2	td(EMHZ-HOLDAL)	Delay time, EMIF Bus high impedance to HOLDA low			ns
4	td(HOLDH-EMLZ)	Delay time, HOLD high to EMIF Bus low impedance			ns
5	td(EMLZ-HOLDAH)	Delay time, EMIF Bus low impedance to HOLDA high			ns
6	td(HOLDL-EKOHZ)	Delay time, HOLD low to ECLKOUTx high impedance		¶	ns
7	td(HOLDH-EKOLZ)	Delay time, HOLD high to ECLKOUTx low impedance			ns

[†] E = the EMIF input clock (ECLKIN, CPU/4 clock, or CPU/6 clock) period in ns.

All pending EMIF transactions are allowed to complete before HOLDA is asserted. If no bus transactions are occurring, then the minimum delay time can be achieved. Also, bus hold can be indefinitely delayed by setting NOHOLD = 1.



† EMIF Bus consists of: CE[3:0], BE[3:0], ED[31:0], EA[21:2], ARE/SDCAS/SADS/SRE, AOE/SDRAS/SOE, and AWE/SDWE/SWE, SDCKE, SOE3, and PDT.

Figure 29. HOLD/HOLDA Timing



[‡] EMIF Bus consists of: CE[3:0], BE[3:0], ED[31:0], EA[21:2], ARE/SDCAS/SADS/SRE, AOE/SDRAS/SOE, and AWE/SDWE/SWE, SDCKE, SOE3, and PDT.

[§] The EKxHZ bits in the EMIF Global Control register (GBLCTL) determine the state of the ECLKOUTx signals during HOLDA. If EKxHZ = 0, ECLKOUTx continues clocking during Hold mode. If EKxHZ = 1, ECLKOUTx goes to high impedance during Hold mode, as shown in Figure 29.

BUSREQ TIMING

switching characteristics over recommended operating conditions for the BUSREQ cycles (see Figure 30)

NO	PARAMETER		-300		
NO.			MAX	UNIT	
1	td(AEKO1H-ABUSRV) Delay time, AECLKOUT1 high to ABUSREQ valid			ns	

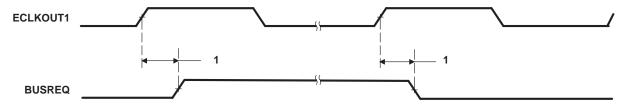


Figure 30. BUSREQ Timing

SPRS196 - MARCH 2002

RESET TIMING

timing requirements for reset[†] (see Figure 31)

NO			-300		
NO.			MIN	MAX	UNIT
1	tw(RST)	Width of the RESET pulse (PLL stable)‡			ns
		Width of the RESET pulse (PLL needs to sync up)§			μs
16	t _{su(boot)}	Setup time, boot configuration bits valid before RESET high¶			ns
17	th(boot)	Hold time, boot configuration bits valid after RESET high¶			ns

 $[\]dagger$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

switching characteristics over recommended operating conditions during reset^{†#||} (see Figure 31)

		PARAMETER		-300	
NO.		MIN	MAX	UNIT	
2	td(RSTL-ECKI)	Delay time, RESET low to ECLKIN synchronized internally			ns
3	td(RSTH-ECKI)	Delay time, RESET high to ECLKIN synchronized internally			ns
4	td(RSTL-ECKO1HZ)	Delay time, RESET low to ECLKOUT1 high impedance			ns
5	td(RSTH-ECKO1V)	Delay time, RESET high to ECLKOUT1 valid			ns
6	td(RSTL-EMIFZHZ)	Delay time, RESET low to EMIF Z high impedance			ns
7	td(RSTH-EMIFZV)	Delay time, RESET high to EMIF Z valid			ns
8	td(RSTL-EMIFHIV)	Delay time, RESET low to EMIF high group invalid			ns
9	td(RSTH-EMIFHV)	Delay time, RESET high to EMIF high group valid			ns
10	td(RSTL-EMIFLIV)	Delay time, RESET low to EMIF low group invalid			ns
11	td(RSTH-EMIFLV)	Delay time, RESET high to EMIF low group valid			ns
12	td(RSTL-LOWIV)	Delay time, RESET low to low group invalid			ns
13	td(RSTH-LOWV)	Delay time, RESET high to low group valid		·	ns
14	td(RSTL-ZHZ)	Delay time, RESET low to Z group high impedance		·	ns
15	t _d (RSTH-ZV)	Delay time, RESET high to Z group valid			ns

[†] P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

EA[21:2], ED[31:0], CE[3:0], BE[3:0], ARE/SDCAS/SADS/SRE, AWE/SDWE/SWE, and AOE/SDRAS/SOE, || EMIF Z group consists of:

SOE3, SDCKE, and PDT.

EMIF high group consists of: HOLDA (when the corresponding HOLD input is high)

Z group consists of:

BUSREQ; HOLDA (when the corresponding HOLD input is low)

EMIF low group consists of: Low group consists of:

XSP CS, XSP CLK, and XSP DO; all of which apply only when PCI EEPROM (EEAI) is enabled

(with PCI_EN = 1). Otherwise, the XSP_CLK and XSP_DO pins are in the Z group. For more details

on the PCI configuration pins, see the Device Configurations section of this data sheet.

HD[31:0]/AD[31:0], CLKX0, CLKX1, XSP_CLK, FSX0, FSX1, DX0, DX1, XSP_DO, CLKR0, CLKR1, FSR0, FSR1, TOUT0, TOUT1, GP[8:0], GP10/PCBE3, HR/W/PCBE2, HDS2/PCBE1, PCBE0, GP13/PINTA, GP11/PREQ, HDS1/PSERR, HCS/PPERR, HCNTL1/PDEVSEL, HAS/PPAR,

HCNTL0/PSTOP, HHWIL/PTRDY (16-bit HPI mode only), HRDY/PIRDY, and HINT/PFRAME.

PRODUCT PREVIEW

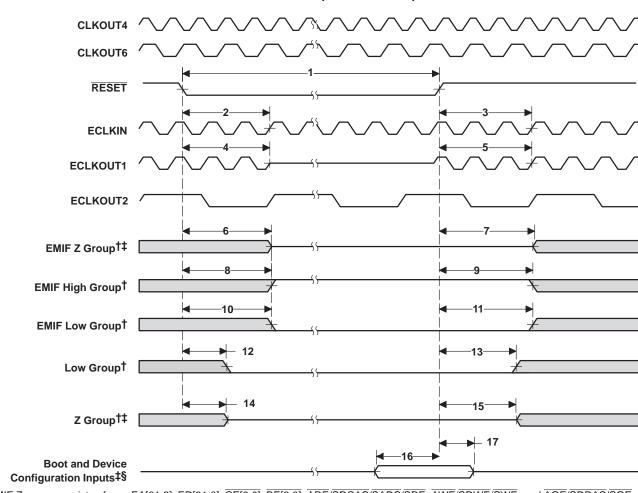


[‡] This parameter applies to CLKMODE x1 when CLKIN is stable, and applies to CLKMODE x6 when CLKIN and PLL are stable.

[§] This parameter applies to CLKMODE x6 only (it does not apply to CLKMODE x1). The RESET signal is not connected internally to the clock PLL circuit. The PLL, however, may need up to 250 µs to stabilize following device power up or after PLL configuration has been changed. During that time. RESET must be asserted to ensure proper device operation. See the clock PLL section for PLL lock times.

 $[\]P$ LEND, BOOTMODE[1:0], ECLKIN_SEL[1:0], EEAI, and HD5/AD5 are the boot configuration pins during device reset.

[#]E = the EMIF input clock (ECLKIN, CPU/4 clock, or CPU/6 clock) period in ns.



RESET TIMING (CONTINUED)

† EMIF Z group consists of: EA[21:2], ED[31:0], CE[3:0], BE[3:0], ARE/SDCAS/SADS/SRE, AWE/SDWE/SWE, and AOE/SDRAS/SOE,

SOE3, SDCKE, and PDT.

EMIF high group consists of: HOLDA (when the corresponding HOLD input is high)

EMIF low group consists of: BUSREQ; HOLDA (when the corresponding HOLD input is low)

Low group consists of: XSP_CS, XSP_CLK, and XSP_DO; all of which apply only when PCI EEPROM (EEAI) is enabled

(with PCI_EN = 1). Otherwise, the XSP_CLK and XSP_DO pins are in the Z group. For more details

on the PCI configuration pins, see the Device Configurations section of this data sheet.

Z group consists of: HD[31:0]/AD[31:0], CLKX0, CLKX1, XSP_CLK, FSX0, FSX1, DX0, DX1, XSP_DO, CLKR0, CLKR1,

FSR0, FSR1, TOUT0, TOUT1, GP[8:0], GP10/PCBE3, HR/W/PCBE2, HDS2/PCBE1, PCBE0, GP13/PINTA, GP11/PREQ, HDS1/PSERR, HCS/PPERR, HCNTL1/PDEVSEL, HAS/PPAR,

HCNTL0/PSTOP, HHWIL/PTRDY (16-bit HPI mode only), HRDY/PIRDY, and HINT/PFRAME.

Figure 31. Reset Timing[†]



[‡] If LEND, BOOTMODE[1:0], ECLKIN_SEL[1:0], EEAI, and HD5/AD5 pins are actively driven, care must be taken to ensure no timing contention between parameters 6, 7, 14, 15, 16, and 17.

[§] Boot and Device Configurations Inputs (during reset) include: LEND, BOOTMODE[1:0], ECLKIN_SEL[1:0], EEAI, and HD5/AD5. The PCI_EN pin *must* be driven valid at all times and the user *must not* switch values throughout device operation.

SPRS196 - MARCH 2002

EXTERNAL INTERRUPT TIMING

timing requirements for external interrupts[†] (see Figure 32)

NO			-300	
NO.		MIN	MAX	UNIT
1	t _W (ILOW) Width of the interrupt pulse low			ns
2	t _W (IHIGH) Width of the interrupt pulse high			ns

 $[\]dagger$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.



Figure 32. External/NMI Interrupt Timing

HOST-PORT INTERFACE (HPI) TIMING

timing requirements for host-port interface cycles^{†‡} (see Figure 33 through Figure 40)

			-3	00	LINIT
NO.			MIN	MAX	UNIT
1	tsu(SELV-HSTBL)	Setup time, select signals§ valid before HSTROBE low			ns
2	th(HSTBL-SELV)	Hold time, select signals§ valid after HSTROBE low			ns
3	tw(HSTBL)	Pulse duration, HSTROBE low	¶		ns
4	tw(HSTBH)	Pulse duration, HSTROBE high between consecutive accesses			ns
10	tsu(SELV-HASL)	Setup time, select signals§ valid before HAS low			ns
11	th(HASL-SELV)	Hold time, select signals§ valid after HAS low			ns
12	t _{su(HDV-HSTBH)}	Setup time, host data valid before HSTROBE high			ns
13	th(HSTBH-HDV)	Hold time, host data valid after HSTROBE high			ns
14	^t h(HRDYL-HSTBL)	Hold time, HSTROBE low after HRDY low. HSTROBE should not be inactivated until HRDY is active (low); otherwise, HPI writes will not complete properly.			ns
18	t _{su(HASL-HSTBL)}	Setup time, HAS low before HSTROBE low			ns
19	th(HSTBL-HASL)	Hold time, HAS low after HSTROBE low			ns

[†]HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.

switching characteristics over recommended operating conditions during host-port interface cycles^{†‡} (see Figure 33 through Figure 40)

NO	PARAMETER		-300		
NO.			MIN	MAX	UNIT
5	td(HCS-HRDY)	Delay time, HCS to HRDY#			ns
6	^t d(HSTBL-HRDYH)	Delay time, HSTROBE low to HRDY high			ns
7	td(HSTBL-HDLZ)	Delay time, HSTROBE low to HD low impedance for an HPI read			ns
8	^t d(HDV-HRDYL)	Delay time, HD valid to HRDY low			ns
9	toh(HSTBH-HDV)	Output hold time, HD valid after HSTROBE high			ns
15	^t d(HSTBH-HDHZ)	Delay time, HSTROBE high to HD high impedance			ns
16	td(HSTBL-HDV)	Delay time, HSTROBE low to HD valid (HPI16 only)			ns
17	^t d(HSTBH-HRDYH)	Delay time, HSTROBE high to HRDY high [★]		·	ns

[†]HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.



 $[\]ddagger$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

[§] Select signals include: HCNTL[1:0] and HR/W. For HPI16 mode only, select signals also include HHWIL.

[¶] Select the parameter value of 4P or 12.5 ns, whichever is greater.

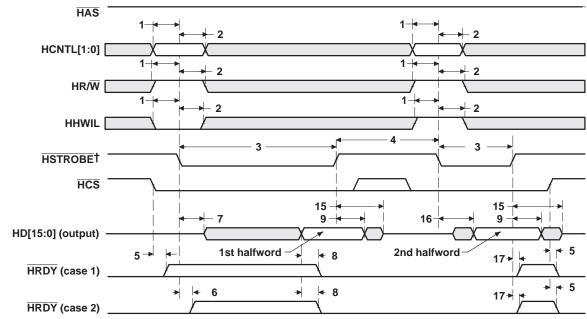
 $[\]ddagger$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

[#] HCS enables HRDY, and HRDY is always low when HCS is high. The case where HRDY goes high when HCS falls indicates that HPI is busy completing a previous HPID write or READ with autoincrement.

This parameter is used during HPID reads and writes. For reads, at the beginning of a word transfer (HPI32) or the first half-word transfer (HPI16) on the falling edge of HSTROBE, the HPI sends the request to the EDMA internal address generation hardware, and HRDY remains high until the EDMA internal address generation hardware loads the requested data into HPID. For writes, HRDY goes high if the internal write buffer is full.

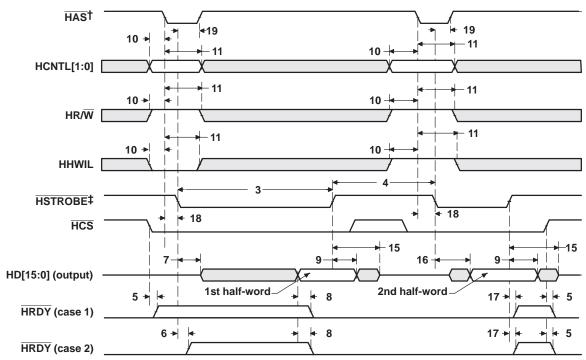
[★]This parameter is used after a word (HPI32) or the second half-word (HPI16) of an HPID write or autoincrement read. HRDY remains low if the access is not an HPID write or autoincrement read. Reading or writing to HPIC or HPIA does not affect the HRDY signal.

HOST-PORT INTERFACE (HPI) TIMING (CONTINUED)



† HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.

Figure 33. HPI16 Read Timing (HAS Not Used, Tied High)



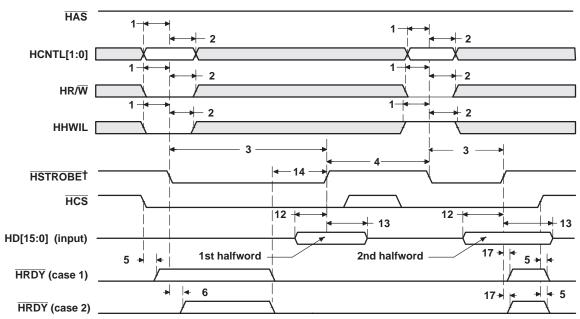
[†] For correct operation, strobe the HAS signal only once per HSTROBE active cycle.

Figure 34. HPI16 Read Timing (HAS Used)



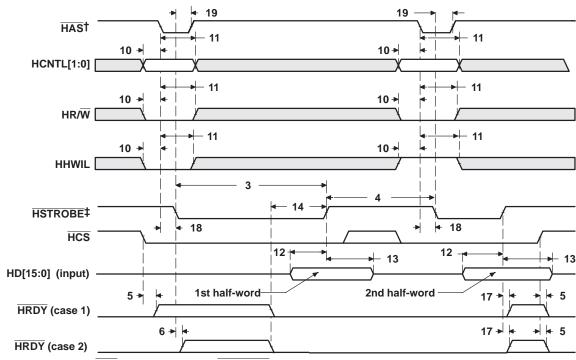
[‡] HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.

HOST-PORT INTERFACE (HPI) TIMING (CONTINUED)



[†]HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.

Figure 35. HPI16 Write Timing (HAS Not Used, Tied High)



 $[\]dagger$ For correct operation, strobe the $\overline{\text{HAS}}$ signal only once per $\overline{\text{HSTROBE}}$ active cycle.

Figure 36. HPI16 Write Timing (HAS Used)



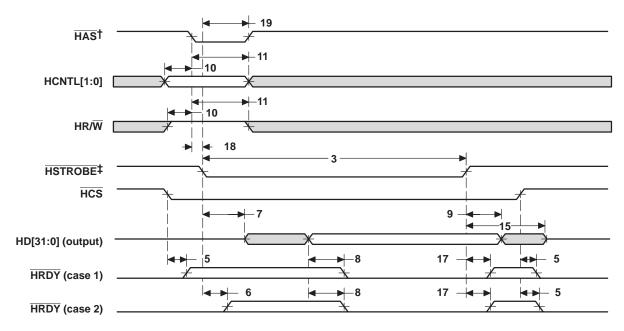
[‡]HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.

HRDY (case 2)

HCNTL[1:0] HR/W HSTROBET HCS HRDY (case 1) HRDY (case 1) HOST-PORT INTERFACE (HPI) TIMING (CONTINUED) HAS 17 + 5 17 + 5

† HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.

Figure 37. HPI32 Read Timing (HAS Not Used, Tied High)



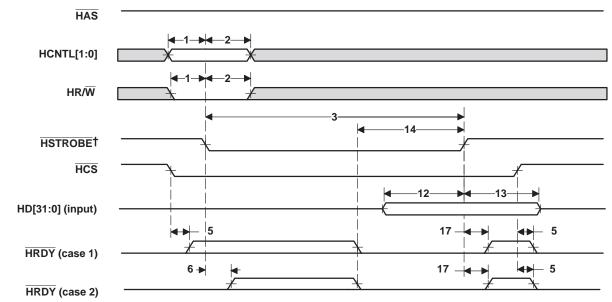
[†] For correct operation, strobe the HAS signal only once per HSTROBE active cycle.

Figure 38. HPI32 Read Timing (HAS Used)



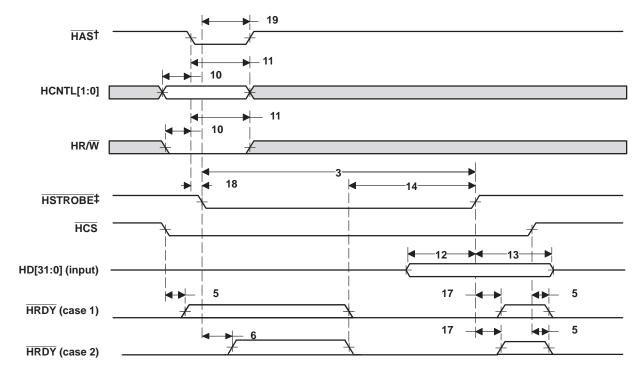
[‡]HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.

HOST-PORT INTERFACE (HPI) TIMING (CONTINUED)



† HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.

Figure 39. HPI32 Write Timing (HAS Not Used, Tied High)



 $[\]dagger$ For correct operation, strobe the $\overline{\text{HAS}}$ signal only once per $\overline{\text{HSTROBE}}$ active cycle.

Figure 40. HPI32 Write Timing (HAS Used)



 $[\]ddagger$ HSTROBE refers to the following logical operation on HCS, HDS1, and HDS2: [NOT(HDS1 XOR HDS2)] OR HCS.

PERIPHERAL COMPONENT INTERCONNECT (PCI) TIMING

timing requirements for PCLK[†] (see Figure 41)

			-300		
NO.			MIN	MAX	UNIT
1	t _C (PCLK)	Cycle time, PCLK			ns
2	tw(PCLKH)	Pulse duration, PCLK high			ns
3	tw(PCLKL)	Pulse duration, PCLK low			ns
4	tsr(PCLK)	$\Delta v/\Delta t$ slew rate, PCLK			V/ns

TFor 3.3 V operation, the reference points for the rise and fall transitions are measured at V_{ILP} MAX and V_{IHP} MIN.

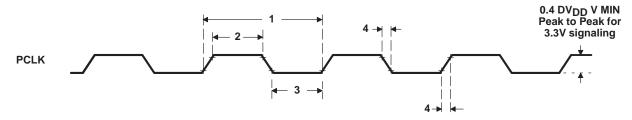


Figure 41. PCLK Timing

timing requirements for PCI reset (see Figure 42)

NO			-30		
NO.			MIN	MAX	UNIT
1	tw(PRST)	Pulse duration, PRST			ms
2	t _{su} (PCLKA-PRSTH)	Setup time, PCLK active before PRST high			μs

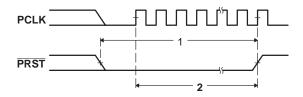


Figure 42. PCI Reset (PRST) Timing

PERIPHERAL COMPONENT INTERCONNECT (PCI) TIMING (CONTINUED)

timing requirements for PCI inputs (see Figure 43)

NO			-30	0	
NO.			MIN	MAX	UNIT
5	t _{su(IV-PCLKH)}	Setup time, input valid before PCLK high			ns
6	th(IV-PCLKH)	Hold time, input valid after PCLK high			ns

switching characteristics over recommended operating conditions for PCI outputs (see Figure 43)

		DADAMETER	-30	00	
NO.	PARAMETER	MIN	MAX	UNIT	
1	td(PCLKH-OV)	Delay time, PCLK high to output valid			ns
2	td(PCLKH-OIV)	Delay time, PCLK high to output invalid			ns
3	td(PCLKH-OLZ)	Delay time, PCLK high to output low impedance			ns
4	td(PCLKH-OHZ)	Delay time, PCLK high to output high impedance			ns

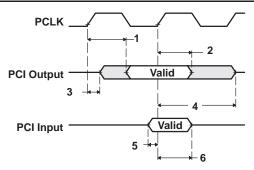


Figure 43. PCI Intput/Output Timing

PERIPHERAL COMPONENT INTERCONNECT (PCI) TIMING (CONTINUED)

timing requirements for serial EEPROM interface (see Figure 44)

NO		-30	0	
NO.		MIN	MAX	UNIT
8	t _{SU(DIV-CLKH)} Setup time, XSP_DI valid before XSP_CLK high			ns
9	th(CLKH-DIV) Hold time, XSP_DI valid after XSP_CLK high			ns

switching characteristics over recommended operating conditions for serial EEPROM interface[†] (see Figure 44)

NO		DADAMETER		-300		
NO.		PARAMETER	MIN	NOM	MAX	UNIT
1	tw(CSL)	Pulse duration, XSP_CS low				ns
2	td(CLKL-CSL)	Delay time, XSP_CLK low to XSP_CS low				ns
3	td(CSH-CLKH)	Delay time, XSP_CS high to XSP_CLK high				ns
4	tw(CLKH)	Pulse duration, XSP_CLK high				ns
5	tw(CLKL)	Pulse duration, XSP_CLK low				ns
6	tosu(DOV-CLKH)	Output setup time, XSP_DO valid after XSP_CLK high				ns
7	toh(CLKH-DOV)	Output hold time, XSP_DO valid after XSP_CLK high				ns

 $[\]overline{\dagger}$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

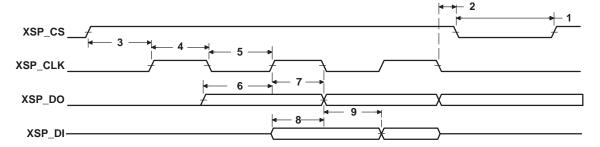


Figure 44. PCI Serial EEPROM Interface Timing

MULTICHANNEL BUFFERED SERIAL PORT (McBSP) TIMING

timing requirements for McBSP^{†‡} (see Figure 45)

NO				-300		LINUT
NO.			_ [MIN	MAX	UNIT
2	t _C (CKRX)	Cycle time, CLKR/X	CLKR/X ext	§		ns
3	tw(CKRX)	Pulse duration, CLKR/X high or CLKR/X low	CLKR/X ext			ns
_		Catura times automod FCD bimb bafara CLVD lavo	CLKR int			
5	tsu(FRH-CKRL)	Setup time, external FSR high before CLKR low	CLKR ext			ns
		Held time a cutomad FCD bink after CLVD law.	CLKR int			
6	th(CKRL-FRH)	Hold time, external FSR high after CLKR low	CLKR ext			ns
_		Output Care DD and the store OLKD laws	CLKR int			
7	tsu(DRV-CKRL)	Setup time, DR valid before CLKR low	CLKR ext			ns
		Hold Care DD wellst effect OLKD laws	CLKR int			
8	th(CKRL-DRV)	Hold time, DR valid after CLKR low	CLKR ext			ns
40		Output time and social EQV high hadens QUVV land	CLKX int			
10	tsu(FXH-CKXL)	Setup time, external FSX high before CLKX low	CLKX ext	_		ns
44		Held Consequence FOV block of the OLKY loss	CLKX int	•		
11	th(CKXL-FXH)	Hold time, external FSX high after CLKX low	CLKX ext	•		ns

[†] CLKRP = CLKXP = FSRP = FSXP = 0. If polarity of any of the signals is inverted, then the timing references of that signal are also inverted.

 $^{^\}ddagger$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

[§] The maximum bit rate for McBSP-to-McBSP communications is 75 MHz; therefore, the minimum CLKR/X clock cycle is either four times the CPU cycle time (4P), or 10 ns (100 MHz), whichever value is larger. For example, when running parts at 300 MHz (P = 3.33 ns), use 13.33 ns (75 MHz) as the minimum CLKR/X clock cycle (by setting the appropriate CLKGDV ratio or external clock source). When running parts at 200 MHz (P = 5 ns), use 4P = 20 ns (50 MHz) as the minimum CLKR/X clock cycle. The maximum bit rate for McBSP-to-McBSP communications applies to the following hardware configuration: the serial port is a Master of the clock and frame syncs (with CLKR connected to CLKX, FSR connected to FSX, CLKXM = FSXM = 1, and CLKRM = FSRM = 0) in data delay 1 or 2 mode (R/XDATDLY = 01b or 10b) and the other device the McBSP communicates to is a Slave.

switching characteristics over recommended operating conditions for McBSP^{†‡} (see Figure 45)

		DADAMETED.		-300)	
NO.		PARAMETER	Ï	MIN	MAX	UNIT
1	td(CKSH-CKRXH)	Delay time, CLKS high to CLKR/X high for internal CLKR/X CLKS input	X generated from			ns
2	t _C (CKRX)			§¶		ns
3	tw(CKRX)	Pulse duration, CLKR/X high or CLKR/X low	CLKR/X int	#	#	ns
4	^t d(CKRH-FRV)	Delay time, CLKR high to internal FSR valid	CLKR int			ns
		D. 1. 1. 2.1.0.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.1.	CLKX int			ns
9	^t d(CKXH-FXV)	Delay time, CLKX high to internal FSX valid	CLKX ext			
40		Disable time, DX high impedance following last data bit	CLKX int			
12	^t dis(CKXH-DXHZ)	from CLKX high	CLKX ext			ns
			CLKX int			
13	^t d(CKXH-DXV)	Delay time, CLKX high to DX valid	CLKX ext			ns
		Delay time, FSX high to DX valid	FSX int			
14	^t d(FXH-DXV)	ONLY applies when in data delay 0 (XDATDLY = 00b) mode	FSX ext			ns

† CLKRP = CLKXP = FSRP = FSXP = 0. If polarity of any of the signals is inverted, then the timing references of that signal are also inverted.

The maximum bit rate for McBSP-to-McBSP communications is 75 MHz; therefore, the minimum CLKR/X clock cycle is either four times the CPU cycle time (4P), or 10 ns (100 MHz), whichever value is larger. For example, when running parts at 300 MHz (P = 3.33 ns), use 13.33 ns (75 MHz) as the minimum CLKR/X clock cycle (by setting the appropriate CLKGDV ratio or external clock source). When running parts at 200 MHz (P = 5 ns), use 4P = 20 ns (50 MHz) as the minimum CLKR/X clock cycle. The maximum bit rate for McBSP-to-McBSP communications applies to the following hardware configuration: the serial port is a Master of the clock and frame syncs (with CLKR connected to CLKX, FSR connected to FSX, CLKXM = FSXM = 1, and CLKRM = FSRM = 0) in data delay 1 or 2 mode (R/XDATDLY = 01b or 10b) and the other device the McBSP communicates to is a Slave.

 $^{\#}C = HorL$

S = sample rate generator input clock = 4P if CLKSM = 1 (P = 1/CPU clock frequency)

= sample rate generator input clock = P_clks if CLKSM = 0 (P_clks = CLKS period)

H = CLKX high pulse width = (CLKGDV/2 + 1) * S if CLKGDV is even

= (CLKGDV + 1)/2 * S if CLKGDV is odd or zero

L = CLKX low pulse width = (CLKGDV/2) * S if CLKGDV is even

= (CLKGDV + 1)/2 * S if CLKGDV is odd or zero

CLKGDV should be set appropriately to ensure the McBSP bit rate does not exceed the maximum limit (see ¶ footnote above).

Extra delay from CLKX high to DX valid applies only to the first data bit of a device, if and only if DXENA = 1 in SPCR.

if DXENA = 0, then D1 = D2 = 0

if DXENA = 1, then D1 = 4P, D2 = 8P



[‡] Minimum delay times also represent minimum output hold times.

[§] P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

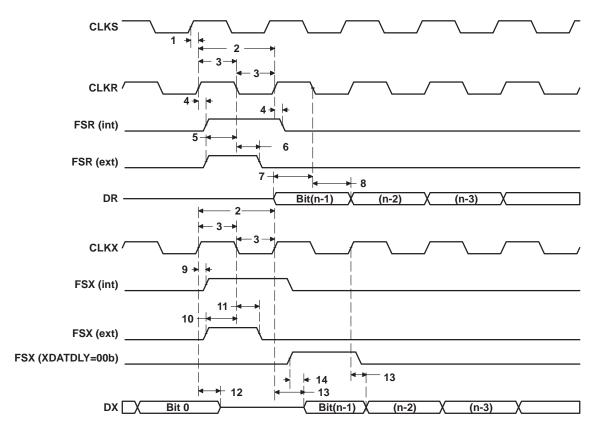


Figure 45. McBSP Timing

TMS320C6411 FIXED-POINT DIGITAL SIGNAL PROCESSOR

SPRS196 - MARCH 2002

MULTICHANNEL BUFFERED SERIAL PORT (McBSP) TIMING (CONTINUED)

timing requirements for FSR when GSYNC = 1 (see Figure 46)

NO		-30	00	
NO.		MIN	MAX	UNIT
1	t _{su(FRH-CKSH)} Setup time, FSR high before CLKS high			ns
2	th(CKSH-FRH) Hold time, FSR high after CLKS high			ns

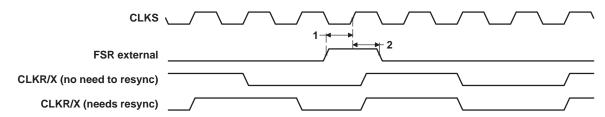


Figure 46. FSR Timing When GSYNC = 1



timing requirements for McBSP as SPI Master or Slave: CLKSTP = 10b, CLKXP = 0^{†‡} (see Figure 47)

				-300		UNIT
NO.		MAS	TER	SLAV	E	UNIT
		MIN	MAX	MIN	MAX	
4	t _{SU(DRV-CKXL)} Setup time, DR valid before CLKX low					ns
5	th(CKXL-DRV) Hold time, DR valid after CLKX low					ns

 $[\]dagger$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

switching characteristics over recommended operating conditions for McBSP as SPI Master or Slave: CLKSTP = 10b, CLKXP = $0^{\dagger \ddagger}$ (see Figure 47)

					-300		
NO.		PARAMETER	MAST	ΓER§	SLA	/E	UNIT
			MIN	MAX	MIN	MAX	
1	th(CKXL-FXL)	Hold time, FSX low after CLKX low¶					ns
2	td(FXL-CKXH)	Delay time, FSX low to CLKX high#					ns
3	td(CKXH-DXV)	Delay time, CLKX high to DX valid					ns
6	t _{dis} (CKXL-DXHZ)	Disable time, DX high impedance following last data bit from CLKX low					ns
7	tdis(FXH-DXHZ)	Disable time, DX high impedance following last data bit from FSX high					ns
8	t _d (FXL-DXV)	Delay time, FSX low to DX valid					ns

 $[\]dagger$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

T = CLKX period = (1 + CLKGDV) * S

H = CLKX high pulse width = (CLKGDV/2 + 1) * S if CLKGDV is even

= (CLKGDV + 1)/2 * S if CLKGDV is odd or zero

L = CLKX low pulse width = (CLKGDV/2) * S if CLKGDV is even

= (CLKGDV + 1)/2 * S if CLKGDV is odd or zero

CLKXM = FSXM = 1, CLKRM = FSRM = 0 for Master McBSP

CLKXM = CLKRM = FSXM = FSRM = 0 for Slave McBSP



[‡] For all SPI Slave modes, CLKG is programmed as 1/4 of the CPU clock by setting CLKSM = CLKGDV = 1.

[‡] For all SPI Slave modes, CLKG is programmed as 1/4 of the CPU clock by setting CLKSM = CLKGDV = 1.

[§]S = Sample rate generator input clock = 4P if CLKSM = 1 (P = 1/CPU clock frequency)

⁼ Sample rate generator input clock = P_clks if CLKSM = 0 (P_clks = CLKS period)

[¶] FSRP = FSXP = 1. As a SPI Master, FSX is inverted to provide active-low slave-enable output. As a Slave, the active-low signal input on FSX and FSR is inverted before being used internally.

[#]FSX should be low before the rising edge of clock to enable Slave devices and then begin a SPI transfer at the rising edge of the Master clock (CLKX).

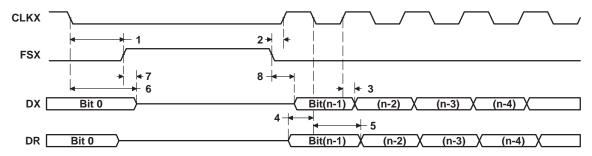


Figure 47. McBSP Timing as SPI Master or Slave: CLKSTP = 10b, CLKXP = 0

timing requirements for McBSP as SPI Master or Slave: CLKSTP = 11b, CLKXP = 0^{†‡} (see Figure 48)

			_	300		
NO.		MAS	TER	SLA	/E	UNIT
		MIN	MAX	MIN	MAX	
4	tsu(DRV-CKXH) Setup time, DR valid before CLKX high					ns
5	th(CKXH-DRV) Hold time, DR valid after CLKX high					ns

 $[\]dagger$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

switching characteristics over recommended operating conditions for McBSP as SPI Master or Slave: CLKSTP = 11b, CLKXP = 0^{+} (see Figure 48)

					-300		
2 t 3 t 6 t	PARAMETER		MAS	ΓER§	SLA	/E	UNIT
			MIN	MAX	MIN	MAX	
1	th(CKXL-FXL)	Hold time, FSX low after CLKX low¶					ns
2	td(FXL-CKXH)	Delay time, FSX low to CLKX high#					ns
3	td(CKXL-DXV)	Delay time, CLKX low to DX valid					ns
6	tdis(CKXL-DXHZ)	Disable time, DX high impedance following last data bit from CLKX low					ns
7	td(FXL-DXV)	Delay time, FSX low to DX valid					ns

[†]P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

T = CLKX period = (1 + CLKGDV) * S

H = CLKX high pulse width = (CLKGDV/2 + 1) * S if CLKGDV is even

= (CLKGDV + 1)/2 * S if CLKGDV is odd or zero

L = CLKX low pulse width = (CLKGDV/2) * S if CLKGDV is even

= (CLKGDV + 1)/2 * S if CLKGDV is odd or zero

CLKXM = FSXM = 1, CLKRM = FSRM = 0 for Master McBSP

CLKXM = CLKRM = FSXM = FSRM = 0 for Slave McBSP

[#]FSX should be low before the rising edge of clock to enable Slave devices and then begin a SPI transfer at the rising edge of the Master clock (CLKX).

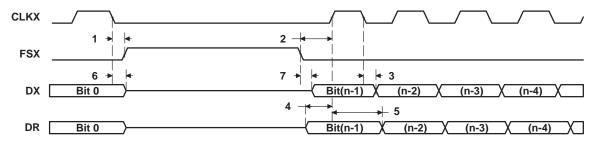


Figure 48, McBSP Timing as SPI Master or Slave: CLKSTP = 11b, CLKXP = 0



[‡] For all SPI Slave modes, CLKG is programmed as 1/4 of the CPU clock by setting CLKSM = CLKGDV = 1.

[‡] For all SPI Slave modes, CLKG is programmed as 1/4 of the CPU clock by setting CLKSM = CLKGDV = 1.

[§] S = Sample rate generator input clock = 4P if CLKSM = 1 (P = 1/CPU clock frequency)

⁼ Sample rate generator input clock = P_clks if CLKSM = 0 (P_clks = CLKS period)

FSRP = FSXP = 1. As a SPI Master, FSX is inverted to provide active-low slave-enable output. As a Slave, the active-low signal input on FSX and FSR is inverted before being used internally.

SPRS196 - MARCH 2002

MULTICHANNEL BUFFERED SERIAL PORT (McBSP) TIMING (CONTINUED)

timing requirements for McBSP as SPI Master or Slave: CLKSTP = 10b, CLKXP = 1^{†‡} (see Figure 49)

			-	-300		
NO.		MAS	TER	SLA\	/E	UNIT
		MIN	MAX	MIN	MAX	
4	t _{su(DRV-CKXH)} Setup time, DR valid before CLKX high					ns
5	th(CKXH-DRV) Hold time, DR valid after CLKX high					ns

[†] P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

switching characteristics over recommended operating conditions for McBSP as SPI Master or Slave: CLKSTP = 10b, CLKXP = 1^{+1} (see Figure 49)

					-300		
NO.		PARAMETER	MAST	TER§	SLA	/E	UNIT
			MIN	MAX	MIN	MAX	
1	th(CKXH-FXL)	Hold time, FSX low after CLKX high¶					ns
2	td(FXL-CKXL)	Delay time, FSX low to CLKX low#					ns
3	td(CKXL-DXV)	Delay time, CLKX low to DX valid					ns
6	tdis(CKXH-DXHZ)	Disable time, DX high impedance following last data bit from CLKX high					ns
7	^t dis(FXH-DXHZ)	Disable time, DX high impedance following last data bit from FSX high					ns
8	td(FXL-DXV)	Delay time, FSX low to DX valid					ns

 $[\]dagger$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

T = CLKX period = (1 + CLKGDV) * S

CLKX high pulse width = (CLKGDV/2 + 1) * S if CLKGDV is even

= (CLKGDV + 1)/2 * S if CLKGDV is odd or zero

L = CLKX low pulse width = (CLKGDV/2) * S if CLKGDV is even

= (CLKGDV + 1)/2 * S if CLKGDV is odd or zero

CLKXM = FSXM = 1, CLKRM = FSRM = 0 for Master McBSP

CLKXM = CLKRM = FSXM = FSRM = 0 for Slave McBSP



[‡] For all SPI Slave modes, CLKG is programmed as 1/4 of the CPU clock by setting CLKSM = CLKGDV = 1.

[‡] For all SPI Slave modes, CLKG is programmed as 1/4 of the CPU clock by setting CLKSM = CLKGDV = 1.

[§] S = Sample rate generator input clock = 4P if CLKSM = 1 (P = 1/CPU clock frequency)

⁼ Sample rate generator input clock = P_clks if CLKSM = 0 (P_clks = CLKS period)

[¶]FSRP = FSXP = 1. As a SPI Master, FSX is inverted to provide active-low slave-enable output. As a Slave, the active-low signal input on FSX and FSR is inverted before being used internally.

[#]FSX should be low before the rising edge of clock to enable Slave devices and then begin a SPI transfer at the rising edge of the Master clock (CLKX).

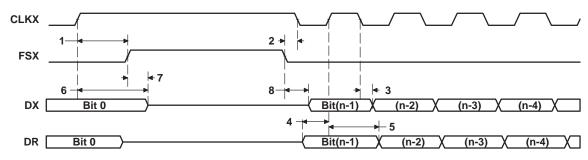


Figure 49. McBSP Timing as SPI Master or Slave: CLKSTP = 10b, CLKXP = 1

PRODUCT PREVIEW

MULTICHANNEL BUFFERED SERIAL PORT (McBSP) TIMING (CONTINUED)

timing requirements for McBSP as SPI Master or Slave: CLKSTP = 11b, CLKXP = 1^{†‡} (see Figure 50)

			_	-300		
NO.		MAS	TER	SLAV	/E	UNIT
		MIN	MAX	MIN	MAX	
4	tsu(DRV-CKXH) Setup time, DR valid before CLKX high					ns
5	th(CKXH-DRV) Hold time, DR valid after CLKX high					ns

 $[\]dagger$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

switching characteristics over recommended operating conditions for McBSP as SPI Master or Slave: CLKSTP = 11b, CLKXP = $1^{1\pm}$ (see Figure 50)

			-		-300		
NO.		PARAMETER	MAST	ΓER§	SLA\	/E	UNIT
			MIN	MAX	MIN	MAX	
1	th(CKXH-FXL)	Hold time, FSX low after CLKX high¶					ns
2	td(FXL-CKXL)	Delay time, FSX low to CLKX low#					ns
3	td(CKXH-DXV)	Delay time, CLKX high to DX valid					ns
6	tdis(CKXH-DXHZ)	Disable time, DX high impedance following last data bit from CLKX high					ns
7	td(FXL-DXV)	Delay time, FSX low to DX valid					ns

 $[\]dagger$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

T = CLKX period = (1 + CLKGDV) * S

H = CLKX high pulse width = (CLKGDV/2 + 1) * S if CLKGDV is even

= (CLKGDV + 1)/2 * S if CLKGDV is odd or zero

L = CLKX low pulse width = (CLKGDV/2) * S if CLKGDV is even

= (CLKGDV + 1)/2 * S if CLKGDV is odd or zero

FSRP = FSXP = 1. As a SPI Master, FSX is inverted to provide active-low slave-enable output. As a Slave, the active-low signal input on FSX and FSR is inverted before being used internally.

CLKXM = FSXM = 1, CLKRM = FSRM = 0 for Master McBSP

CLKXM = CLKRM = FSXM = FSRM = 0 for Slave McBSP

#FSX should be low before the rising edge of clock to enable Slave devices and then begin a SPI transfer at the rising edge of the Master clock (CLKX).



[‡] For all SPI Slave modes, CLKG is programmed as 1/4 of the CPU clock by setting CLKSM = CLKGDV = 1.

For all SPI Slave modes, CLKG is programmed as 1/4 of the CPU clock by setting CLKSM = CLKGDV = 1.

[§]S = Sample rate generator input clock = 4P if CLKSM = 1 (P = 1/CPU clock frequency)

⁼ Sample rate generator input clock = P_clks if CLKSM = 0 (P_clks = CLKS period)

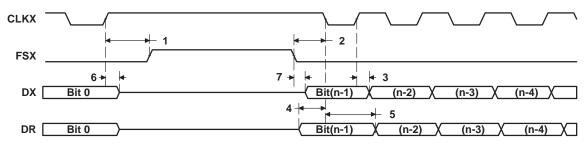


Figure 50. McBSP Timing as SPI Master or Slave: CLKSTP = 11b, CLKXP = 1

timing requirements for timer inputs† (see Figure 51)

NO		-3	00	LINUT
NO.		MIN	MAX	UNIT
1	t _{w(TINPH)} Pulse duration, TINP high			ns
2	t _{W(TINPL)} Pulse duration, TINP low			ns

 $[\]dagger$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

switching characteristics over recommended operating conditions for timer outputs[†] (see Figure 51)

NO	DADAMETED		-300		LINUT
NO.	PARAMETER	MI	1 1	VIAX	UNIT
3	t _{w(TOUTH)} Pulse duration, TOUT high				ns
4	t _{w(TOUTL)} Pulse duration, TOUT low				ns

 \dagger P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

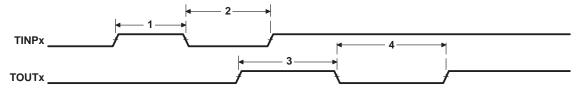


Figure 51. Timer Timing

GENERAL-PURPOSE INPUT/OUTPUT (GPIO) PORT TIMING

timing requirements for GPIO inputs[†] (see Figure 52)

NO		-30	00	
NO.		MIN	MAX	UNIT
1	t _W (GPIH) Pulse duration, GPIx high			ns
2	t _{w(GPIL)} Pulse duration, GPIx low			ns

 $[\]dagger$ P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

switching characteristics over recommended operating conditions for GPIO outputs[†] (see Figure 52)

NO	PARAMETER	-300			
NO.		PARAMETER	MIN	MAX	UNIT
3	t _W (GPOH) Pulse duration, Gl	POx high		·	ns
4	t _W (GPOL) Pulse duration, G	POx low			ns

 \dagger P = 1/CPU clock frequency in ns. For example, when running parts at 300 MHz, use P = 3.33 ns.

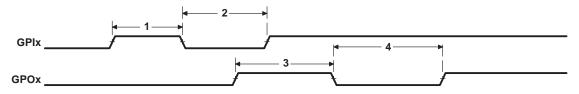


Figure 52. GPIO Port Timing

JTAG TEST-PORT TIMING

timing requirements for JTAG test port (see Figure 53)

			-30	00	
NO.			MIN	MAX	UNIT
1	t _C (TCK)	Cycle time, TCK			ns
3	t _{su} (TDIV-TCKH)	Setup time, TDI/TMS/TRST valid before TCK high			ns
4	th(TCKH-TDIV)	Hold time, TDI/TMS/TRST valid after TCK high			ns

switching characteristics over recommended operating conditions for JTAG test port (see Figure 53)

NO	D. PARAMETER -	-30	-300	
NO.	PARAMETER		MAX	UNIT
2	t _d (TCKL-TDOV) Delay time, TCK low to TDO valid			ns

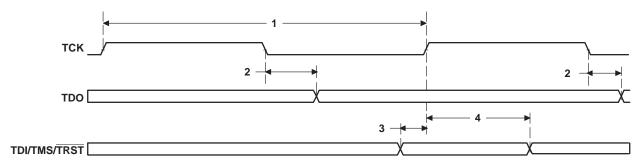
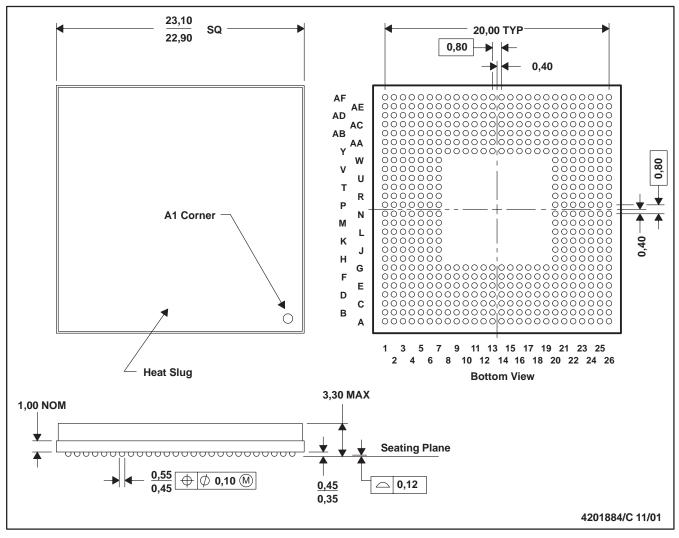


Figure 53. JTAG Test-Port Timing

MECHANICAL DATA

GLZ (S-PBGA-N532)

PLASTIC BALL GRID ARRAY



NOTES: A. All linear dimensions are in millimeters.

- B. This drawing is subject to change without notice.
- C. Thermally enhanced plastic package with heat slug (HSL)
- D. Flip chip application only

thermal resistance characteristics (S-PBGA package)

NO			°C/W	Air Flow (m/s [†])
1	RΘJC	Junction-to-case	1.4	N/A
2	R⊝JB	Junction-to-board	4.9	0.00
3	RΘJA	Junction-to-free air	17.5	0.00
4	RΘJA	Junction-to-free air	14.5	0.75
5	RΘJA	Junction-to-free air	12.5	1.25
6	RΘJA	Junction-to-free air	10.4	2.00
7	PsiJT	Junction-to-package top	0.7	N/A
8	Psi _{JB}	Junction-to-board	4.5	N/A

† m/s = meters per second



IMPORTANT NOTICE

Texas Instruments Incorporated and its subsidiaries (TI) reserve the right to make corrections, modifications, enhancements, improvements, and other changes to its products and services at any time and to discontinue any product or service without notice. Customers should obtain the latest relevant information before placing orders and should verify that such information is current and complete. All products are sold subject to TI's terms and conditions of sale supplied at the time of order acknowledgment.

TI warrants performance of its hardware products to the specifications applicable at the time of sale in accordance with TI's standard warranty. Testing and other quality control techniques are used to the extent TI deems necessary to support this warranty. Except where mandated by government requirements, testing of all parameters of each product is not necessarily performed.

TI assumes no liability for applications assistance or customer product design. Customers are responsible for their products and applications using TI components. To minimize the risks associated with customer products and applications, customers should provide adequate design and operating safeguards.

TI does not warrant or represent that any license, either express or implied, is granted under any TI patent right, copyright, mask work right, or other TI intellectual property right relating to any combination, machine, or process in which TI products or services are used. Information published by TI regarding third—party products or services does not constitute a license from TI to use such products or services or a warranty or endorsement thereof. Use of such information may require a license from a third party under the patents or other intellectual property of the third party, or a license from TI under the patents or other intellectual property of TI.

Reproduction of information in TI data books or data sheets is permissible only if reproduction is without alteration and is accompanied by all associated warranties, conditions, limitations, and notices. Reproduction of this information with alteration is an unfair and deceptive business practice. TI is not responsible or liable for such altered documentation.

Resale of TI products or services with statements different from or beyond the parameters stated by TI for that product or service voids all express and any implied warranties for the associated TI product or service and is an unfair and deceptive business practice. TI is not responsible or liable for any such statements.

Mailing Address:

Texas Instruments Post Office Box 655303 Dallas, Texas 75265